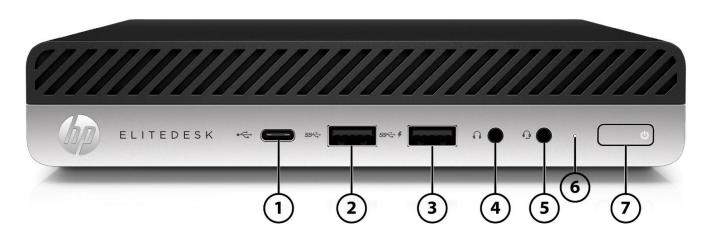
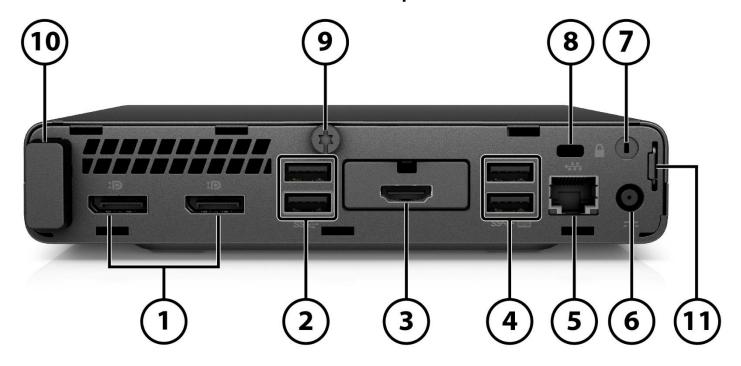
HP EliteDesk 705 G4 Desktop Mini Business PC



- 1. USB Type-C™ port with Fast Charging
- 2. USB 3.1 Gen 1 Type A (5 Gbit/s data speed)
- 3. USB 3.1 Gen 1 Type A (charging port) (5 Gbit/s data speed)
- 4. Headset Connector

- 5. Universal Audio Jack with CTIA headset support
- 6. Hard Drive activity light
- 7. Dual-state power button

HP EliteDesk 705 G4 Desktop Mini Business PC



- 1. DisplayPort™ 1.2
- 2. USB 3.1 Gen 1 (5GBits/s) Type A
- 3. Configurable Option card slot (Choice of DisplayPort™ 1.2, HDMI™ 2.0, VGA, USB Type-C™ with alt mode display, Discrete Graphics Option Card with DisplayPort™ 11. 1.4) (Availability depends on model)
- USB 3.1 Gen 1 (5GBits/s) Type A 4. allows for wake from S4/S5 with keyboard/mouse when connected and enabled in BIOS
- 5. **RJ-45 Network Adapter**
- 6. Power connector

Not Shown

10.

Slots (1) Internal M.2 2230 connector for WLAN

(1) Internal M.2 SSD storage (2230 or 2280 connector)

Bays (1) 2.5- inch SATA drive Bay

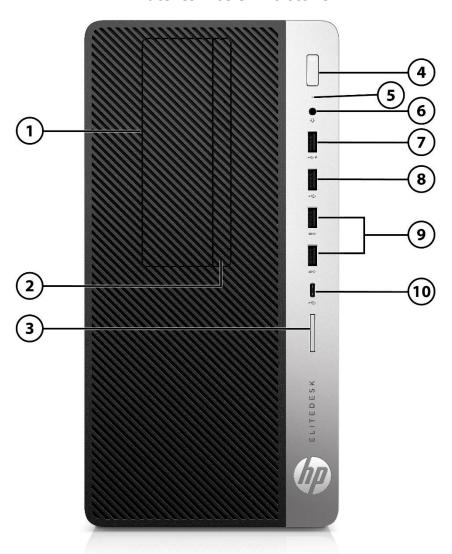
Mounting Support for

- VESA Sleeve
- Quick Release Bracket
- B300/B500 Mounting bracket

- 7. WLAN External Antenna Punchout
- 8. Universal Cable Lock Slot
- 9. **Cover Release Thumbscrew**
 - **WLAN Internal Antenna**
 - Padlock Loop



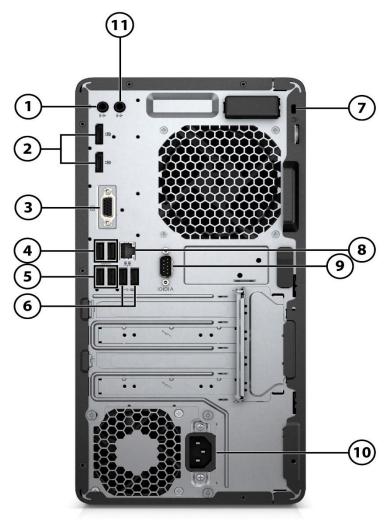
HP EliteDesk 705 G4 Microtower



- 1. 5.25-inch Half-Height Drive Bay (behind bezel)
- 2. Slim optical drive (optional)
- 3. SD 4 Card Reader (optional)
- 4. Dual-state power button
- 5. Hard Drive activity light

- 6. Headphone connector
- 7. USB 2.0 port (fast charging port)
- 8. USB 2.0 port
- 9. USB 3.1 Gen 1 ports (2) (5 Gbit/s data speed)
- 10. USB Type-C™ port (10 Gbit/s data speed)

HP EliteDesk 705 G4 Microtower



- 1. Audio-out jack for powered audio devices
- 2. Dual-Mode DisplayPort™ 1.2 (2)
- 3. Optional port (DisplayPort™ 1.2, HDMI, VGA or USB Type-C™) (USB-C™ option has alt mode DisplayPort™ 1.2 or 15W output) shown here with VGA port installed
- 4. USB 3.1 Gen1 ports (2) (5 Gbit/s data speed)
- 5. USB 2.0 ports (2)

- 6. USB 2.0 ports with wake from S4 (2)
- 7. Cable lock slot
- 8. RJ-45 Network Adapter
- 9. Optional serial port shown here installed
- 10. Power connector
- 11. Audio-in

Not shown

Bave

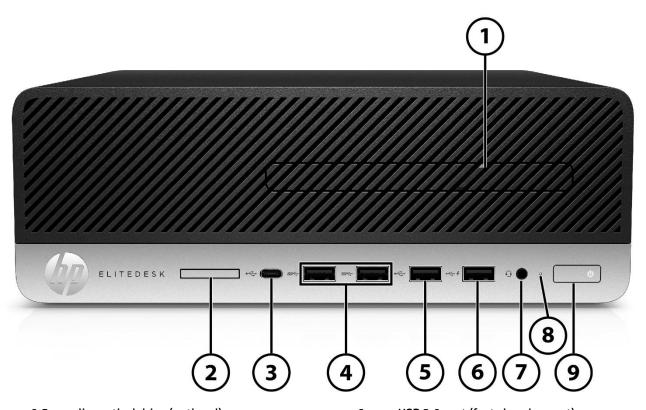
- (2) 2.5" internal storage drive bay
- (1) 3.5" internal storage drive bay (convertible to 2.5")
- (1) 9.5mm slim optical drive bay
- (1) 5.25" external half-height drive bay

Slots

- (1) PCI Express x16 graphics connectors
- (3) PCI Express x1
- (1) internal M.2 SSD storage (2230 or 2280 connector)
- (1) internal M.2 WLAN (2230 connector)

Standard Features and Configurable Components (availability may vary by country)

HP EliteDesk 705 G4 Small Form Factor Business PC

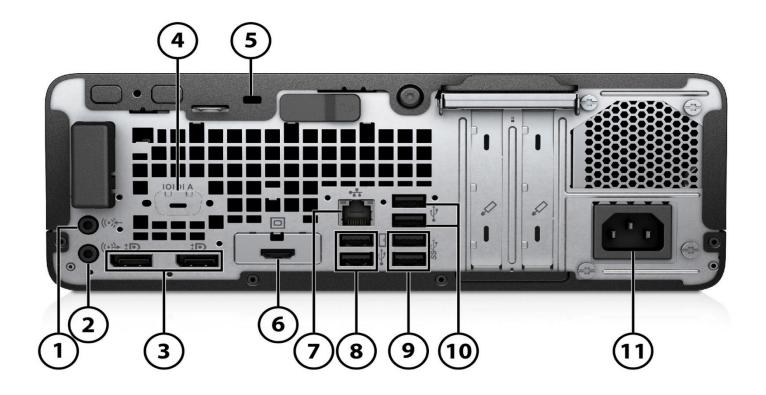


- 1. 9.5mm slim optical drive (optional)
- 2. SD 4 card reader (optional)
- 3. USB Type-C[™] charging port
- 4. USB 3.1 Gen 1 ports (2) (5 Gbit/s data speed)
- 5. USB 2.0 port

- 6. USB 2.0 port (fast charging port)
- 7. Universal Audio Jack with CTIA headset support
- 8. Hard Drive activity light
- 9. Dual-state power button

Standard Features and Configurable Components (availability may vary by country)

HP EliteDesk 705 G4 Small Form Factor Business PC



- 1. Audio-in connector
- 2. Audio-out connector for powered audio devices
- 3. Dual-Mode DisplayPort™ 1.2 (2)
- 4. Serial Port shown here not installed
- 5. Cable lock slot
- Optional port (DisplayPort™ 1.2, HDMI, VGA or USB Type-C™) (USB-C™ option has alt mode DisplayPort™ 1.2 or 15W output) shown here with HDMI port installed
- 7. RJ-45 Network Adapter
- 8. USB 2.0 ports with wake from S4 (2)
- 9. USB 3.1 Gen 1 (2) (5 Gbit/s data speed)
- 10. USB 2.0 (2)
- 11. Power connector

Not shown

- (1) 3.5" internal storage drive bay (convertible to two 2.5")
- (1) 9.5mm slim optical drive bay

Slots

- (1) PCI Express x16 graphics connectors
- (1) PCI Express x1
- (1) internal M.2 SSD storage (2230 or 2280 connector)
- (1) internal M.2 WLAN (2230 connector)

Standard Features and Configurable Components (availability may vary by country)

AT A GLANCE

- Choice of three form factors: Microtower, Small Form Factor and Desktop Mini
- Latest AMD® Ryzen™ PRO Processor with Radeon™ Vega Graphics¹
- 7th generation of AMD® Pro A-Series APU4
- DDR4 Synchronous Dynamic Random Access Memory (SDRAM) (Transfer rates up to 2933 MT/s)¹
- Processor support up to 65W on DM; up to 95W on MT/SFF
- Integrated AMD® Radeon™ Vega Graphics (AMD® Radeon™ on 7th gen) and optional Radeon™ RX discrete graphics
- Support for up to three monitors via two standard DisplayPort™ 1.2 connectors with multi-stream² and an optional third video port connector which provides the following choices: HDMI, VGA, DisplayPort™ 1.2, or USB Type-C™ with DisplayPort™ 1.2 for all platforms; USB Type-C™ with DisplayPort™ 1.2 for 705 G4 DM 35W (see Ports section for port availability by platform)
- Selection of discrete graphic cards to configure systems to up to 7 displays (MT, SFF and DM 35W)
- AMD® Radeon™ discrete graphics enabling viewing immersive VR
- MT and SFF models can be configured with dual data drives in a RAID (limited configurations)
- Industry-standard AMD® DASH manageability
- HP Sure Click
- HP Sure Start Gen4
- HP Sure Run
- HP Sure Recover
- HP BIOSphere Gen4
- HP Client Security Manager Gen4
- HP WorkWise
- High efficiency energy saving power supply options
- ENERGY STAR® certified. EPEAT® Gold registered where applicable/supported. Registration may vary by country. See
- http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options.
- CCC, CECP and SEPA Certified
- PC chassis and all internal components and modules are manufactured with low halogen content³
- Arsenic-free
- Dust filter available (MT, SFF and DM 35W)
- Lengthy purchase lifecycles and image stability
- Protected by HP Services, including limited warranties up to 3-3-3 (terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Integrated Conexant Audio Codec
- 1. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed.
- 2. DisplayPort™ multi-stream monitors 'daisy-chained' together.
- 3. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be low halogen.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Standard Features and Configurable Components (availability may vary by country)

PRODUCT NAME

HP EliteDesk 705 G4 Microtower Business PC HP EliteDesk 705 G4 Small Form Factor Business PC HP EliteDesk 705 G4 Desktop Mini Business PC

OPERATING SYSTEM

Preinstalled Windows® 10 Pro 64¹

Windows® 10 Pro 64 (National Academic License)²

Windows® 10 Home 641

Windows® 10 Home Single Language 641

FreeDos 2.0

- 1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.
- 2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com

CHIPSET

	<u>DM</u>	<u>SFF</u>	<u>MT</u>
AMD® B350 FCH	Х	Х	X



Standard Features and Configurable Components (availability may vary by country)

PROCESSORS

7th Generation of AMD® Pro A-Series APU¹	<u>DM</u>	<u>SFF</u>	<u>MT</u>
AMD® PRO A6-9500E APU with AMD® Radeon™ Graphics (3.0 GHz, 1MB, 35W, Dual core)	X		
AMD® PRO A6-9500 APU with AMD® Radeon™ Graphics (3.5 GHz, 1MB, 65W, Dual core)		X	Х
AMD® PRO A8-9600 APU with AMD® Radeon™ Graphics (3.1 GHz, 2MB, 65W, Quad Core)		X	X
AMD® PRO A10-9700E APU with AMD® Radeon™ Graphics (3.0 GHz, 2MB, 35W, Quad Core)	X		
AMD® PRO A10-9700 APU with AMD® Radeon™ Graphics (3.5 GHz, 2MB, 65W, Quad Core)		X	Х
AMD® PRO A10-9700E APU with AMD® Radeon™ Graphics (3.0 GHz, 2MB, 35W, Quad Core)	X		

^{1.} Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. AMD's numbering is not a measurement of clock speed.

GRAPHICS

AMD® Ryzen™ with AMD®Radeon™ Vega Graphics APU and CPU¹	<u>DM</u>	<u>SFF</u>	<u>MT</u>
AMD® Ryzen™ 3 PRO 2200GE APU AMD®Radeon™ Vega Graphics Quad-Core (3.6 GHz, 6MB, 35W, Quad Core)	X		
AMD® Ryzen™ 3 PRO 2200G APU with AMD®Radeon™ Vega Graphics (3.7 GHz, 6MB, 65W, Quad Core)	X	Х	X
AMD® Ryzen™ 5 PRO 2400GE APU with AMD®Radeon™ Vega Graphics (3.8 GHz, 6MB, 35W, Quad Core)	X		
AMD® Ryzen™ 5 PRO 2400G APU with AMD®Radeon™ Vega Graphics (3.9 GHz, 6MB, 65W, Quad Core)	Х	Х	X

^{1.} AMD® Ryzen PRO CPU requires discrete graphic card attached.

STORAGE

3.5 inch SATA Hard Disk Drives (HDD)	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HDD 1TB 7200RPM SATA-3 3.5in		Х	Х
HDD 2TB 7200RPM SATA-3 3.5in		Х	Х
HDD 500GB 7200RPM 3.5in		Х	Х
HP 1TB 7200rpm 3.5 SATA 6.0Gb/s NCQ Smart IV Hard Drive (16MB)		Х	Х
HP 500GB 7200rpm 3.5 SATA 6.0Gb/s Smart IV Hard Drive	-	X	X

2.5 inch SATA Hard Disk Drives (HDD)	<u>DM</u>	<u>SFF</u>	<u>MT</u>
500 GB 5400RPM 2.5in SATA SSHD	Х	Х	Х
1 TB 5400RPM 2.5in SATA SSHD	Х	X	X
2 TB 5400RPM 2.5in SATA SSHD			Х



Standard Features and Configurable Components (availability may vary by country)

.5 inch Solid State Drives (SSD)	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HDD 500GB 7200RPM 2.5in	Х	X	X
HDD 1TB 7200RPM 2.5in	Х	X	X
HDD 2TB 5400RPM 2.5in		X	X
HDD 500GB 7200RPM 2.5in Self Encrypted Drive OPAL2	Х	X	X
HDD 500GB 7200RPM 2.5in Federal Information Processing Standard	Х	X	X
5 inch SATA Solid State Hybrid Drives (SSHD)	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HDD 500GB 5400RPM 2.5in SSHD	<u> </u>	<u> </u>	∏ <u>x</u>
HDD 1TB 5400RPM 2.5in SSHD	X	X	X
HDD 2TB 5400RPM 2.5in SSHD			
			<u> </u>
.5 inch Solid State Drives (SSD)	<u>DM</u>	<u>SFF</u>	<u>MT</u>
SSD 128GB 2.5in SATA Three Layer Cell	Х	X	Х
SSD 256GB 2.5in SATA Three Layer Cell	Х	Х	Х
SSD 512GB 2.5in SATA Three Layer Cell	Х	Х	Х
SSD 256GB 2.5in SATA Self Encrypted OPAL2 TLC	Х	X	Х
SSD 512GB 2.5in SATA Self Encrypted OPAL2 TLC	Х	Х	Х
SSD 256GB 2.5in Federal Information Processing Standard	Х	Х	Х
SSD 512GB 2.5in Federal Information Processing Standard	Х	X	Х
1.2 PCIe NMVe Solid State Drives (SSD)	<u>DM</u>	<u>SFF</u>	<u>MT</u>
SSD 128GB M.2 2280 PCIe NVMe		Х	Х
SSD 256GB M.2 2280 PCIe NVMe	Х	Х	Х
SSD 512GB M.2 2280 PCIe NVMe	Х	X	Х
SSD 128GB M.2 2280 PCIe-3x2 NVMe Three Layer Cell		X	Х
SSD 256GB M.2 2280 PCIe NVMe Three Layer Cell	X	X	Х
SSD 512GB M.2 2280 PCIe NVMe Three Layer Cell	Х	X	Х
SSD 1TB M.2 2280 PCIe NVMe Three Layer Cell	Х	Х	Х
SSD 256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell	Х	X	Х
SSD 512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell		X	Х
SSD Intel Optane 118GB 2280 PCIe NVMe (Optane)		X	Х
HP 9.5mm Slim DVD-ROM Drive		X	Х
HP 9.5mm Slim SuperMulti DVD Writer Drive		X	Х
THE STATE OF THE S			Х
HP 9.5mm Slim Blu-Ray Writer Drive		X	^
HP 9.5mm Slim Blu-Ray Writer Drive		X	
	<u>DM</u>	SFF X	<u>MT</u>

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Standard Features and Configurable Components (availability may vary by country)

MEMORY

x Memory Configuration	<u>DM</u>	<u>SFF</u>	<u>MT</u>
	Х		
DDR4-2666 (Transfer rates up to 2666 MT/s), 32 GB, 2 SODIMM ¹	Х		
DDR4-2666 (Transfer rates up to 2666 MT/s), 64 GB, 4 DIMM		X	Х

nory Configuration	<u>DM</u>	<u>SFF</u>	<u>MT</u>
4GB (1x4GB) 2666 DDR4 1.2v DIMM		X	Х
8GB (2x4GB) 2666 DDR4 1.2v DIMM		X	Х
8GB (1x8GB) 2666 DDR4 1.2v DIMM		X	Х
16GB (2x8GB) 2666 DDR4 1.2v DIMM		X	Х
16GB (1x16GB) 2666 DDR4 1.2v DIMM		X	Х
32GB (2x16GB) 2666 DDR4 1.2v DIMM		X	X
32GB (4x8GB) 2666 DDR4 1.2v DIMM		X	Х
64GB (4x16GB) 2666 DDR4 1.2v DIMM		X	X
	<u>DM</u>	<u>SFF</u>	<u>MT</u>
4 GB (1 x 4 GB) 2666 DDR4 SODIMM ¹	Х		
8 GB (2 x 4 GB) 2666 DDR4 SODIMM ¹	Х		
8 GB (1 x 8 GB) 2666 DDR4 SODIMM ¹	Х		
16 GB (2 x 8 GB) 2666 DDR4 SODIMM ¹	Х	·	
16 GB (1 x 16 GB) 2666 DDR4 SODIMM ¹	Х		
32 GB (2 x 16 GB) 2666 DDR4 SODIMM ¹	X	-	

^{1.} Transfer rates up to 2400 MT/s: for processors with AMD Pro A-Series APU; Transfer rates up to 2666MT/s: for processors with AMD Ryzen™ with AMD Radeon™.



Standard Features and Configurable Components (availability may vary by country)

NETWORKING/COMMUNICATIONS

Ethernet (RJ-45)	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Realtek® RTL8111EPH (standard)	Х	Х	Х
Wireless ¹	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Intel® 3168 802.11 AC 1x1 with Bluetooth® 4.0 (Brazil)	Х	X	
Intel® 7265 802.11AC 2x2 with Bluetooth® M.2 Combo Card non-vPro™ (Brazil)	Х	X	
Intel® 9260 802.11 AC 2x2 +Bluetooth® 5 PCIe non-vPro™	Х	X	X
Realtek® 802.11 AC 1x1 with Bluetooth® 4.2 LE M.2 PCIe	Х	Х	Х
Realtek® 802.11 AC 2x2 with Bluetooth® 4.2 LE M.2 PCIe		X	Х

^{1.} Wireless access point and Internet service required and not included. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices

KEYBOARDS AND POINTING DEVICES

Keyboards	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HP Conferencing USB Keyboard	X	X	X
HP Wireless Collaboration Keyboard	X	Х	X
HP USB and PS/2 Washable Keyboard	X	Х	X
HP USB Smart Card (CCID) Keyboard	X	X	X
HP USB Business Slim Keyboard	X	Х	X
HP USB Keyboard	X	Х	X
HP PS/2 Business Slim Keyboard		Х	X
HP Wireless Business Slim Keyboard and Mouse	X	Х	X

use	<u>DM</u>	<u>SFF</u>	<u>MT</u>
HP PS/2 Mouse		Х	X
HP USB Optical Mouse	X	Х	X
HP USB Premium Mouse	X	Х	X
HP 1000dpi Laser Mouse USB	X	Х	X
HP USB and PS/2 Washable Mouse	X	X	X
Antimicrobial USB Mouse ¹	X	Х	X
HP Hardened USB Mouse ¹	X	Х	X

^{1.} Not available in all regions



Мо

Standard Features and Configurable Components (availability may vary by country)

SECURITY

	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Trusted Platform Module (TPM) 2.0 (Infineon SLB9670). Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified	х	Х	х

PORTS

I/O Ports – Standard	<u>DM</u>	<u>SFF</u>	<u>MT</u>
USB 2.0	N/A	2 including 1 fast charging (front); 4 including 2 wake from S4 (rear)	2 including 1 fast charging (front); 4 including 2 wake from S4 (rear)
USB 3.1 Gen 1	2 front; 4 rear	2 front; 2 rear	2 front; 2 rear
USB 3.0 Type-C™	1 front; 1 rear (option)	1 front; 1 rear (option)	1 front; 1 rear (option)
Video	2 DisplayPort™ 1.2 (rear), 1 Configurable video port (rear) (Choice of DisplayPort™ 1.4, HDMI™ 2.0, VGA, or USB Type- C™ with alt mode display) For models with discrete graphics: 1 DisplayPort™ 1.4 (rear)	2 DisplayPort™ 1.2 (rear), 1 Configurable video port (rear) (Choice of DisplayPort™ 1.2, HDMI™ 2.0, VGA, or USB Type-C™ with alt mode display port or 15W output)	2 DisplayPort™ 1.2 (rear), 1 Configurable video port (rear) (Choice of DisplayPort™ 1.2, HDMI™ 2.0, VGA, USB Type-C™ with alt mode display port or 15W output)
Audio	1 Headset (front), 1 Universal Audio Jack with CTIA headset support (front)	1 Headset (front); 1 Audio-out (rear), 1 Audio-in (rear)	1 Headset (front); 1 Audio-out (rear), 1 Audio-in (rear)
Network Interface	RJ45	RJ45	RJ45

I/O Ports – Optional	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Serial (RS-232)	1 (rear)(option)	1 (rear) (option)	1 (rear) (option)
Serial (RS-232) and PS/2 combination	N/A	1 (rear) (option)	1 (rear) (option)

I/O Ports – Internal Ports	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Internal SATA storage connector(s)	N/A	3	4
Internal SATA storage connector(s)	N/A	3	4
Internal SATA storage connector (Data and Power)	1	N/A	N/A

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

Standard Features and Configurable Components (availability may vary by country)

Slots	<u>DM</u>	<u>SFF</u>	<u>MT</u>
M.2 PCIe	(1) M.2 PCIe x1 2230 (for WLAN) (1) M.2 PCIe x2 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (1) M.2 PCIe x2 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (1) M.2 PCIe x2 2280/2230 Combo (for storage)
PCI Express x1 (v3.0)	N/A	1	3
PCI Express x16 (v3.0)	N/A	1	1
Bays	<u>DM</u>	<u>SFF</u>	<u>MT</u>
5.25" Half Height ODD	N/A	N/A	1
9.5mm Slim ODD	N/A	1	1
Secure Digital (SD) Reader	N/A	1	1
2.5" internal storage drive	1 (optional)	23	2
3.5" internal storage drive	N/A	1	1

NOTE: SFF can be configured with either (1) 3.5" or (2) 2.5" internal storage drive (2.5 inch drive needs adapter)

NOTE: The MT can support a single graphics card up to 75W. When configured with dual graphics cards support is limited to 35W for each.

Standard Features and Configurable Components (availability may vary by country)

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

BIOS

HP BIOSphere Gen4¹⁷
HP DriveLock & Automatic DriveLock
BIOS Update via Network
Master Boot Record Security
Power On Authentication
HP Secure Erase¹⁸
Absolute Persistence Module¹⁹
Pre-boot Authentication
HP Wireless Wakeup

Software

HP Native Miracast Support¹⁵
HP LAN-Wireless Protection
HP Velocity
HP ePrint Driver + JetAdvantage²⁰
HP Hotkey Support – CMIT
HP Recovery Manager
HP Jumpstart
HP Support Assistant²¹
HP Noise Cancellation Software
HP PhoneWise²⁹
Buy Office

Manageability Features

HP Driver Packs²²
HP System Software Manager (SSM)
HP BIOS Config Utility (BCU)
HP Client Catalog
HP Manageability Integration Kit Gen2²³
Ivanti Management Suite²⁴

Client Security Software

HP Client Security Suite Gen4²⁵ including: HP Security Manager²⁶ (including Credential Manager, HP Password Manager, HP Spare Key) HP Device Access Manager HP Power On Authentication Microsoft Defender²⁷

Security Management

HP Secure Erase¹⁸

TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified)³² SATA 0.1 port disablement (viaBIOS)

RAID configurations³³

Serial, USB enable/disable (viaBIOS)

Power-on password (viaBIOS)

Setup password (viaBIOS)

Support for chassis padlocks and cable lock devices

Integrated hood sensor

HP Sure Start Gen430

HP Sure Run³⁵

HP Sure Recover³⁶



- 15. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming
- 17. HP BIOSphere Gen4 requires Intel® or AMD® 8th Gen processors. Features may vary depending on the platform and configurations.
- 18. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method.
- 19. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

 20. HP ePrint Driver requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported
- 20. HP ePrint Driver requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see www.hp.com/go/eprintcenter). Print times and connection speeds may vary.
- 21. HP Support Assistant requires Windows and Internet access.
- 22. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 23. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html
- 24. Ivanti Management Suite subscription required.
- 25. HP Client Security Suite Gen 4 requires Windows and Intel® or AMD® 8th generation processors.
- 26. HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.
- 27. Microsoft Defender Opt in and internet connection required for updates.
- 29. HP PhoneWise Client is only available on select platforms. For supported platforms and HP PhoneWise system requirements see http://www.hp.com/qo/HPPhoneWise.
- 30. HP Sure Start Gen4 is available on HP EliteDesk products equipped with Intel® 8th generation or AMD processors
- 32. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).
- 33. RAID configuration is optional and does require a second hard drive.
- 35. HP Sure Run is available on HP Elite products equipped with 8th generation Intel® or AMD® processors.
- 36. HP Sure Recover is available on HP Elite PCs with 8th generation Intel® or AMD® processors and requires an open, wired network connection. Not available on platforms with multiple internal storage drives, Intel® Optane™. You must back up important files, data, photos, videos, etc. before use to avoid loss of data.



Standard Features and Configurable Components (availability may vary by country)

ENVIRONMENTAL & INDUSTRY

Environmental Data HP EliteDesk 700 Desktop Mini G4 series

Eco-Label Certifications	This product has received or is in the process of being certified to the following approvals and may be					
& declarations	labeled with one or more of these marks:					
a acctarations	• IT ECO declaration					
		• US ENERGY STAR®				
	• EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options .					
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the					
System configuration	Desktop model is based on a "Typio					
Energy Consumption						
(in accordance with US						
ENERGY STAR® test						
method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz			
Normal Operation (Short	10.789	10.858	10.739			
idle)						
Normal Operation (Long	10.488	10.538	10.458			
idle)						
Sleep	0.815	0.851	0.81			
Off	0.756	0.809	0.74			
	NOTE: Energy efficiency data listed	l is for an ENERGY STAR® comp	liant product if offered within the			
	model family. HP computers marke					
	U.S. Environmental Protection Age					
	family does not offer ENERGY STAF					
	for a typically configured PC featur					
	Microsoft Windows® operating syst		referrey power suppry, and a			
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz			
Normal Operation (Short	36.7905	37.0258	36.62			
idle)	30.7303	37.0230	30.02			
Normal Operation (Long	35.7641	35.9346	35.6618			
idle)	33.7041	33.3340	33.0010			
Sleep	2.7792	2.9019	2.7621			
Off	2.7792	2.7587	2.5234			
UII						
	NOTE: Heat dissipation is calculate	a based on the measured watt	s, assuming the service level is			
Dealered Naise	attained for one hour. Sound Power		Cound Duocouna			
Declared Noise			Sound Pressure			
Emissions	(L _{WAd} , bels)		(L _{pAm} , decibels)			
(in accordance with						
ISO 7779 and ISO 9296)						
Typically Configured –	3.1		20			
Idle						
Fixed Disk – Random	4.4		33			
writes	т,т					
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:					
	Spare parts are available througho production.	ut the warranty period and or f	or up to "5" years after the end of			
Batteries	This battery(s) in this product comp	oly with EU Directive 2006/66/	EC			
	Batteries used in the product do no	t contain:				
	Mercury greater the1ppm by weight					
	Cadmium greater than 20ppm by weight					



	Battery size: CR2032 (coin cell)			
	Battery type: Lithium			
Additional Information	•	t is in compliance with the Restrictions of Hazardous Sub	stances (RoHS) directive -	
	2011/65/EC.			
	-	duct is designed to comply with the Waste Electrical and E	electronic Equipment (WEEE)	
	Directive – 20	ouz/96/EC. It is in compliance with California Proposition 65 (State of	California: Safo Drinking Water	
	•	forcement Act of 1986).	California, Safe Drinking Water	
		·	the saulds level in the U.S.	
	• This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level in the U.S. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options</gold>			
		ts weighing over 25 grams used in the product are marke		
		t contains 0% post-consumer recycled plastic (by wt.)	•	
	This produce	t is 95.1% recycle-able when properly disposed of at end	of life.	
Packaging Materials	External:	PAPER/Corrugated		
	Internal:	PLASTIC/EPE (Expanded Polyethylene)		
		PLASTIC/Polyethylene low density		
Material Usage	This product	does not contain any of the following substances in exces	s of regulatory limits (refer to	
_	the HP Gener	al Specification for the Environment at	-	
		hp.com/hpinfo/globalcitizenship/environment/pdf/gse.po	lf):	
	• Asbestos			
	Certain Azo Colorants			
	Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Certain Brominated Flame Retardants – may not be used as flame retardants in plastics			
	• Cadmium			
	Chlorinated Hydrocarbons Chlorinated Paraffins			
	• Formaldeh			
		ed Diphenyl Methanes		
		nates and sulfates		
		ead compounds		
		kide Batteries		
	• Nickel – fin	ishes must not be used on the external surface designed t	o be frequently handled or	
	carried by th	e user.		
		eting Substances		
		nated Biphenyls (PBBs)		
	Polybrominated Biphenyl Ethers (PBBEs)			
	Polybrominated Biphenyl Oxides (PBBOs)			
	Polychlorinated Biphenyl (PCB)			
	Polychlorinated Terphenyls (PCT) Polych			
	• Polyvinyl Chloride (PVC) — except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.			
	Radioactive	• •		
		(TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)		
Packaging Usage		nese quidelines to decrease the environmental impact of p	product packaging:	
		ne use of heavy metals such as lead, chromium, mercury a		
	materials.	ile use of fleavy filetats such as teau, chi officini, filercury a	and cadmidin in packaging	
		no use of exene-deploting substances (ODS) in packaging	matorials	
		he use of ozone-depleting substances (ODS) in packaging	ווומנפו ומנג.	
		kaging materials for ease of disassembly.		
		he use of post-consumer recycled content materials in pa		
		recyclable packaging materials such as paper and corruga		
		e and weight of packages to improve transportation fuel e		
	 Plastic pack 	kaging materials are marked according to ISO 11469 and [DIN 6120 standards.	

Standard Features and Configurable Components (availability may vary by country)

End-of-life Management
and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP 0EM customers who integrate and re-sell HP equipment.

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_ Certificate.pdf

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

Environmental Data HP EliteDesk 700 Slim Form Factor G4 series

Eco-Label Certifications		This product has received or is in the process of being certified to the following approvals and may be			
& declarations	labeled with one or more of these	marks:			
	IT ECO declaration				
	US ENERGY STAR®				
	• EPEAT® Gold registered in the Ur	nited States. See http://www.epea	t.net for registration status in		
	your country. Search keyword gen	erator on HP's 3rd party option sto	ore for solar generator		
	accessories at http://www.hp.com	n/go/options.			
System Configuration	The configuration used for the Eng	ergy Consumption and Declared No	oise Emissions data for the		
	Desktop model is based on a "Typ	ically Configured Desktop".			
Energy Consumption					
(in accordance with US					
ENERGY STAR® test					
method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz		
Normal Operation (Short idle)	22.49	22.24	22.35		
Normal Operation (Long	21.1	21.25	20.87		
idle)					
Sleep	1.05	1.06	1.05		
Off	1.08	1.09	1.08		
	NOTE: Energy efficiency data liste model family. HP computers mark U.S. Environmental Protection Age family does not offer ENERGY STA for a typically configured PC featu Microsoft Windows® operating sys	ed with the ENERGY STAR® Logo a ency (EPA) ENERGY STAR® specifica R® compliant configurations, then ring a hard disk drive, a high efficie stem.	re compliant with the applicable ations for computers. If a model energy efficiency data listed is ency power supply, and a		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz		
Normal Operation (Short idle)	76.6909	75.8384	76.2135		
Normal Operation (Long idle)	71.951	72.4625	71.1667		
Sleep	3.5805	3.6146	3.5805		
Off	3.6828	3.7169	3.6828		
	NOTE: Heat dissipation is calculate attained for one hour.	ed based on the measured watts, a	ssuming the service level is		

Declared Noise		Sound Power		Sound Pressure		
Emissions		(L _{WAd} , bels)		(L _{pAm} , decibels)		
(in accordance with		(LWAU, DCt3)		(Lipanii, accidets)		
ISO 7779 and ISO 9296)						
Typically Configured –		2.0		20		
Idle		3.9		28		
Fixed Disk – Random		4.4		33		
writes						
Longevity and Upgrading		is product can be upgraded, possibly extending its useful life by several years. Upgradeable atures and/or components contained in the product may include:				
	production.	are available throughout the warra	,	to "5" years after the end of		
Batteries	This battery(s) in this product comply with EU D	rective 2006/66/EC			
		ed in the product do not contain:				
		nter the1ppm by weight				
	Cadmium gre	eater than 20ppm by weight				
	Rattery size:	CR2032 (coin cell)				
	Battery type:					
Additional Information		t is in compliance with the Restrict	ions of Hazardous Subs	stances (RoHS) directive -		
	2011/65/EC.					
		duct is designed to comply with the	Waste Electrical and E	Electronic Equipment (WEEE)		
	Directive – 20					
		t is in compliance with California P	oposition 65 (State of	California; Safe Drinking Water		
		forcement Act of 1986).	00 (EDEAT) at a site of a t	de la della		
	• This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level in the U See http://www.epeat.net for registration status by country. Search keyword generator on HP'</gold>					
		store for solar generator accessori				
		ts weighing over 25 grams used in				
		ct contains 0% post-consumer recy		a per 130 11 103 ana 130 10 13.		
		t is 95.1% recycle-able when prope		of life.		
Packaging Materials	External:	PAPER/Corrugated				
	Internal:	PLASTIC/EPE (Expanded Polyeth	ulana)			
	internat.		<u> </u>			
Material Usage	This product	PLASTIC/Polyethylene low densi does not contain any of the followi		es of rogulatory limits (rofor to		
riaterial usaye		al Specification for the Environmer		is of regulatory limits (refer to		
		hp.com/hpinfo/globalcitizenship/e		lf):		
	• Asbestos	p.co,p o, g.co.a.ccp, c.	σσ, μα, 3σσ.μσ	•••		
	• Certain Azo	Colorants				
	Certain Brominated Flame Retardants – may not be used as flame retardants in plastics					
	• Cadmium					
		l Hydrocarbons				
	Chlorinated Formulated					
	Formaldehyde Halogenated Diphenyl Methanes					
		nates and sulfates				
		ead compounds				
		kide Batteries				
		ishes must not be used on the exte	rnal surface designed t	o be frequently handled or		
	carried by the		,			
	• Ozone Depl	eting Substances				
	_	nated Biphenyls (PBBs)				
	Polybromin	nated Biphenyl Ethers (PBBEs)				



	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB) Polychlorinated Tarakaryla (PCT)
	Polychlorinated Terphenyls (PCT) Polywinyl Chlorida (PVC) except for wires and cables and cortain retail packaging has been
	• Polyvinyl Chloride (PVC) — except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
	Radioactive Substances
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging
	materials.
	Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	Design packaging materials for ease of disassembly.
	Maximize the use of post-consumer recycled content materials in packaging materials.
	Use readily recyclable packaging materials such as paper and corrugated materials.
	Reduce size and weight of packages to improve transportation fuel efficiency.
	• Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To
and Recycling	recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_ Certificate.pdf
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

Standard Features and Configurable Components (availability may vary by country)

Environmental Data HP EliteDesk 700 MicroTower G4 series

	liteDesk 700 MicroTower G4 ser			la da a a a a a a a a a a a a a a a a a			
Eco-Label Certifications	This product has received or is in the process of being certified to the following approvals and may be						
& declarations		labeled with one or more of these marks:					
	• IT ECO declaration						
	• US ENERGY STAR®						
	• EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in						
	your country. Search keyword generator on HP's 3rd party option store for solar generator						
	accessories at http://www.hp.com/go/options.						
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the						
System comigaration	Desktop model is based on a "Typically Configured Desktop".						
Energy Consumption							
(in accordance with US							
ENERGY STAR® test							
method)	115VAC, 60Hz	230VAC,	50Hz	100VAC, 50Hz			
Normal Operation (Short	1134AC, 00112	230VAC,	30112	100VAC, 30HZ			
	22.22	22.68	32	23.569			
idle)							
Normal Operation (Long	21.409	21.43	32	21.753			
idle)							
Sleep	1.3327	1.257		1.2692			
Off	0.9518	0.882	25	0.9171			
	NOTE: Energy efficiency data listed	d is for an ENERGY S	TAR® compliant pr	roduct if offered within the			
	model family. HP computers mark						
	U.S. Environmental Protection Age						
	family does not offer ENERGY STA						
	for a typically configured PC feature		e, a high efficiency	power supply, and a			
	Microsoft Windows® operating sys						
Heat Dissipation*	115VAC, 60Hz	115VAC, 60Hz 230VAC, 50Hz 100VAC, 50Hz					
Normal Operation (Short	75.7702	75.7702 77.3456 80.3703					
idle)	73.7702	77.54.	50	00.5705			
Normal Operation (Long	72.0047	72.00	24	74 1777			
idle)	73.0047	73.083	31	74.1777			
Sleep	4.5445	4.289	34	4.328			
Off	3.2456	3.009		3.1273			
OH	NOTE: Heat dissipation is calculate						
	· ·	ia pasea on the mea	isureu watts, assu	ming the service level is			
	attained for one hour.						
Declared Noise	Sound Power			ound Pressure			
Emissions	(L _{WAd} , bels)		(L	_{-pAm} , decibels)			
(in accordance with							
ISO 7779 and ISO 9296)							
Typically Configured –	2.0			20			
Idle	3.9			28			
Fixed Disk – Random							
writes	4.4			33			
	This product can be upgraded ass	cibly outonding its :	ucoful life by sover	ral years. Upgradeable			
Longevity and Upgrading	This product can be upgraded, pos			at years. Opgradeable			
	features and/or components conta	aniea in the product	may include:				
		_					
	Spare parts are available through	out the warranty per	riod and or for up t	o "5" years after the end of			
	production.						
Batteries	This battery(s) in this product com	ply with EU Directiv	e 2006/66/EC				
	Batteries used in the product do no	ot contain:					
	Mercury greater the 1 ppm by weigh						
	caumium greater than 20ppm by V	veignt	Cadmium greater than 20ppm by weight				
	Battery size: CR2032 (coin cell)						



	Battery type: Lithium					
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC. 					
		• This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water				
		and Toxic Enforcement Act of 1986).				
		• This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level in the U.S.</gold>				
		ww.epeat.net for registration status by country. Search ke				
		store for solar generator accessories at http://www.hp.co				
		ts weighing over 25 grams used in the product are marked toontains 0% post-consumer recycled plastic (by wt.)	per 1501 1469 and 150 1043.			
		t is 95.1% recycle-able when properly disposed of at end	of life			
Packaging Materials	External:	PAPER/Corrugated	or the.			
	Internal:	PLASTIC/EPE (Expanded Polyethylene)				
		PLASTIC/Polyethylene low density				
Material Usage		does not contain any of the following substances in exces	s of regulatory limits (refer to			
		al Specification for the Environment at np.com/hpinfo/globalcitizenship/environment/pdf/gse.pd	t).			
	• Asbestos	ip.com/npiino/globalcilizensnip/environment/pui/gse.pu	17.			
	Certain Azo	Colorants				
			ardants in plastics			
	• Cadmium	Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium				
		Hydrocarbons				
	 Chlorinated 					
	 Formaldehy 					
		d Diphenyl Methanes				
		nates and sulfates				
		ead compounds				
	Mercuric Ox					
		shes must not be used on the external surface designed to	o be frequently handled or			
	carried by the					
		eting Substances ated Biphenyls (PBBs)				
		ated Biphenyl Ethers (PBBEs)				
		ated Biphenyl Oxides (PBBOs)				
		ated Biphenyl (PCB)				
		ated Diprietly (1 CB) ated Terphenyls (PCT)				
		nloride (PVC) – except for wires and cables, and certain ret	ail packaging has been			
		emoved from most applications.				
	Radioactive					
	• Tributyl Tin	(TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)				

Standard Features and Configurable Components (availability may vary by country)

Packaging Usage HP follows these quidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. End-of-life Management HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To and Recycling recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/qo/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP EliteDesk 705 G4 Microtower Business PC

Eco-Label Certifications	This product has received or is in the process of being certified to the following approvals and may be			
& declarations	labeled with one or more of these marks:			
	IT ECO declaration			
	• US ENERGY STAR®			
	• EPEAT® Gold registered in the Ur	nited States. See http://www.epeat	.net for registration status in	
		erator on HP's 3rd party option sto		
	accessories at http://www.hp.com/go/options.			
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a Typically Configured Notebook.			
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation (Short idle)	22.22 W	22.68 W	23.57 W	
Normal Operation (Long idle)	21.41 W	21.43 W	21.75 W	
Sleep	1.33 W	1.26 W	1.27 W	
Off	0.95 W	0.88 W	0.92 W	

	NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicabl U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a mode family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.			
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation (Short idle)	76 BTU/hr	78 BTU/hr	81 BTU/hr	
Normal Operation (Long idle)	73 BTU/hr	73 BTU/hr	74 BTU/hr	
Sleep	5 BTU/hr	4 BTU/hr	4 BTU/hr	
Off	3 BTU/hr	3 BTU/hr	3 BTU/hr	
	NOTE: Heat dissipation is calculat attained for one hour.	ed based on the measured watt	s, assuming the service level is	
Declared Noise	Sound Power		Sound Pressure	
Emissions (in accordance with ISO 7779 and ISO 9296)	(L _{WAd} , bels)		(L _{pAm} , decibels)	
Typically Configured – Idle	3.3		25	
Fixed Disk – Random writes	3.3 25			
Batteries	features and/or components contained in the product may include: 3 USB ports 1 PC card slot (type I/II) 1 ExpressCard/54 slot 1 IEEE 1394 Port 2 SODIMM memory slots Optional expansion base docking station 1 multi-bay II storage port Interchangeable HDD Spare parts are available throughout the warranty period and or for up to 5 years after the end of production.			
batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium			
Additional Information	Directive – 2002/96/EC. This product is in compliance wi and Toxic Enforcement Act of 198 This product is in compliance wi See http://www.epeat.net for reg party option store for solar gener	omply with the Waste Electrical th California Proposition 65 (Sta 36). th the IEEE 1680 (EPEAT) standa istration status by country. Searator accessories at http://www.grams used in the product are m	and Electronic Equipment (WEEE) te of California; Safe Drinking Water and at the <gold> level in the U.S. arch keyword generator on HP's 3rd hp.com/go/options harked per ISO11469 and ISO1043.</gold>	

	• This product is 95.1% recycle-able when properly disposed of at end of life.		
Packaging Materials	External:	PAPER/Corrugated	1272 g
	Internal:	PLASTIC/Polyethylene Expanded - EPE	280 g
		PLASTIC/Polyethylene low density – LDPE	28 g
Material Usage	PLASTIC/Polyethylene low density – LDPE This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): Asbestos Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl (PCB) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances		
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. 		ry and cadmium in packaging ing materials. packaging materials. rugated materials. el efficiency. nd DIN 6120 standards.
End-of-life Management and Recycling	recycle your sales office. manner. The EU WEE each product is posted on may be used integrate ar	rs end-of-life HP product return and recycling programs product, please go to: http://www.hp.com/go/reuse-re Products returned to HP will be recycled, recovered or E directive (2002/95/EC) requires manufacturers to prost type for use by treatment facilities. This information (a the Hewlett Packard web site at: http://www.hp.com/gd by recyclers and other WEEE treatment facilities as we ad re-sell HP equipment.	ecycle or contact your nearest HP disposed of in a responsible vide treatment information for (product disassembly instructions) go/recyclers. These instructions



Standard Features and Configurable Components (availability may vary by country)

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_
Certificate.pdf
and
http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP EliteDesk 705 G4 Small Form Factor Business PC

Eco-Label Certifications	This product has received or is in the process of being certified to the following approvals and may be			
& declarations	labeled with one or more of these marks:			
	• IT ECO declaration			
	• US ENERGY STAR®			
	• EPEAT® Gold registered in the Unit	ed States. See http://www.epea	t.net for registration status in	
	your country. Search keyword gene	rator on HP's 3rd party option st	ore for solar generator	
	accessories at http://www.hp.com/		-	
System Configuration	The configuration used for the Ener	gy Consumption and Declared N	oise Emissions data for the	
	Notebook model is based on a Typic	ally Configured Notebook.		
Energy Consumption				
(in accordance with US				
ENERGY STAR® test				
method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation	22.49 W	22.24 W	23.35 W	
(Short idle)				
Normal Operation	21.10 W	21.25 W	20.87 W	
(Long idle)				
Sleep	1.05 W	1.06 W	1.05 W	
Off	1.08 W	1.09 W	1.08 W	
	for a typically configured PC featuri Microsoft Windows® operating syst	em.		
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation	77 BTU/hr	76 BTU/hr	80 BTU/hr	
(Short idle)				
Normal Operation	72 BTU/hr	73 BTU/hr	71 BTU/hr	
(Long idle)				
Sleep	4 BTU/hr	4 BTU/hr	4 BTU/hr	
Off	4 BTU/hr	4 BTU/hr	4 BTU/hr	
	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is			
	attained for one hour.			
Declared Noise	Sound Power		Sound Pressure	
Emissions	(L _{WAd} , bels)		(L _{pAm} , decibels)	
(in accordance with ISO 7779 and ISO 9296)				
Typically Configured – Idle	3.4		26	
Fixed Disk – Random writes	3.4		26	
Longevity and Upgrading	This product can be upgraded, poss features and/or components contai • 3 USB ports		everal years. Upgradeable	

	1		
	• 1 PC card sl	• •	
	• 1 ExpressCa		
	• 1 IEEE 1394		
	• 2 SODIMM r		
		pansion base docking station	
	_	Il storage port	
	Interchange	eable HDD	
			6 6
		are available throughout the warranty period and or for up	to 5 years after the end of
	production.	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC	
	Datteries use	d in the product do not contain.	
		ed in the product do not contain:	
		iter the1ppm by weight eater than 20ppm by weight	
	Caumum gre	eater than 20ppin by weight	
	Rattery size:	CR2032 (coin cell)	
	Battery type:		
Additional Information		t is in compliance with the Restrictions of Hazardous Sub	stances (RoHS) directive -
Additional information	2011/65/EC.		stances (Norts) an ective
		duct is designed to comply with the Waste Electrical and E	Flectronic Equipment (WFFF)
	Directive – 20		teetrome Equipment (WEEE)
		t is in compliance with California Proposition 65 (State of	California: Safe Drinking Water
		forcement Act of 1986).	camonna, sare simming water
		t is in compliance with the IEEE 1680 (EPEAT) standard at	the <gold> level in the U.S.</gold>
		ww.epeat.net for registration status by country. Search ke	
		store for solar generator accessories at http://www.hp.co	
		ts weighing over 25 grams used in the product are marke	
		t contains 0% post-consumer recycled plastic (by wt.)	
		t is 95.1% recycle-able when properly disposed of at end	of life.
Packaging Materials	External:	PAPER/Corrugated	1170 g
	Internal:	PLASTIC/Polyethylene low density – LDPE	17 g
	mternat.		<u> </u>
	T1.1.	PAPER/Paper Color	378 g
Material Usage		does not contain any of the following substances in exces	ss of regulatory limits (refer to
		al Specification for the Environment at	14).
		np.com/hpinfo/globalcitizenship/environment/pdf/gse.pc	11).
	AsbestosCertain Azo	Coloranto	
		minated Flame Retardants – may not be used as flame rei	tardante in plactice
	• Cadmium	minated I tame Netal dants — may not be used as itame ref	tardants in plastics
		l Hydrocarbons	
	Chlorinated		
	Formaldehy		
		d Diphenyl Methanes	
		nates and sulfates	
		ead compounds	
	Mercuric 0x	· ·	
	• Nickel – fini	shes must not be used on the external surface designed t	o be frequently handled or
	carried by the	e user.	
		eting Substances	
	1 - 1 - 1	ated Biphenyls (PBBs)	
i contraction of the contraction			
	Polybromin	ated Biphenyl Ethers (PBBEs)	
	PolybrominPolybromin	ated Biphenyl Ethers (PBBEs) ated Biphenyl Oxides (PBBOs)	
	PolybrominPolybrominPolychlorin	ated Biphenyl Ethers (PBBEs)	



Standard Features and Configurable Components (availability may vary by country)

	 Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP EliteDesk 705 G4 Desktop Mini Business PC

Eco-Label Certifications	This product has received or is in the process of being certified to the following approvals and may be			
& declarations	labeled with one or more of these	labeled with one or more of these marks:		
	IT ECO declaration			
	• US ENERGY STAR®			
	• EPEAT® Gold registered in the U	nited States. See http://www.epeat	.net for registration status in	
	your country. Search keyword generator on HP's 3rd party option store for solar generator			
	accessories at http://www.hp.com/go/options.			
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a Typically Configured Notebook.			
_				
Energy Consumption				
(in accordance with US				
ENERGY STAR® test				
method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz	
Normal Operation	10.79 W	10.86 W	10.74 W	
(Short idle)				
Normal Operation	10.49 W	10.54 W	10.46 W	
(Long idle)				
Sleep	0.82 W	0.85 W	0.81 W	



Off	0.76 W 0.81 W 0.74W			
	model family. HP computers mark U.S. Environmental Protection Age family does not offer ENERGY STA	ed with the ENERGY STA ency (EPA) ENERGY STAF R® compliant configura ring a hard disk drive, a	R [®] compliant product if offered within the AR [®] Logo are compliant with the applicable R [®] specifications for computers. If a model tions, then energy efficiency data listed is high efficiency power supply, and a	
Heat Dissipation*	115VAC, 60Hz	230VAC, 50H	z 100VAC, 60Hz	
Normal Operation (Short idle)	37 BTU/hr	37 BTU/hr	37 BTU/hr	
Normal Operation (Long idle)	36 BTU/hr	36 BTU/hr	36 BTU/hr	
Sleep	3 BTU/hr	3 BTU/hr	3 BTU/hr	
Off	3 BTU/hr	3 BTU/hr	3 BTU/hr	
	attained for one hour.	ed based on the measur	ed watts, assuming the service level is	
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L _{WAd} , bels)		Sound Pressure (L _{pAm} , decibels)	
Typically Configured – Idle	3.1		20	
Fixed Disk – Random writes	3.4		23	
Longevity and Upgrading	features and/or components cont. 3 USB ports 1 PC card slot (type I/II) 1 ExpressCard/54 slot 1 IEEE 1394 Port 2 SODIMM memory slots Optional expansion base docking 1 multi-bay II storage port Interchangeable HDD Spare parts are available throughorduction.	ained in the product mages	and or for up to 5 years after the end of	
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight			
	Battery size: CR2032 (coin cell) Battery type: Lithium			

Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.			
	Directive – 20			
		t is in compliance with California Proposition 65 (S	tate of California; Safe Drinking Wate	
		forcement Act of 1986).		
		t is in compliance with the IEEE 1680 (EPEAT) stan		
		ww.epeat.net for registration status by country. So		
		store for solar generator accessories at http://ww		
		ts weighing over 25 grams used in the product are t contains 0% post-consumer recycled plastic (by		
		t is 95.1% recycle-able when properly disposed of		
Packaging Materials	External:	PAPER/Corrugated	322 g	
	Internal:	PLASTIC/Polyethylene low density – LDPE	5 g	
		PLASTIC/Polyethylene Expanded - EPE	33 g	
1aterial Usage		does not contain any of the following substances	n excess of regulatory limits (refer to	
		al Specification for the Environment at		
		hp.com/hpinfo/globalcitizenship/environment/pdf	/gse.pdf):	
	• Asbestos • Certain Azo	Colorante		
			amo rotardante in plactice	
	 Certain Brominated Flame Retardants – may not be used as flame retardants in plastics Cadmium 			
	Cadmium Chlorinated Hydrocarbons			
	Chlorinated Aydrocarbons Chlorinated Paraffins			
	• Formaldehyde			
	Halogenated Diphenyl Methanes			
	Lead carbonates and sulfates			
	Lead and Lead compounds			
	Mercuric Oxide Batteries			
	• Nickel – finishes must not be used on the external surface designed to be frequently handled or			
	carried by the user.			
		eting Substances		
	Polybrominated Biphenyls (PBBs) (PBBs)			
	Polybrominated Biphenyl Cycles (PBBCs) Polybrominated Biphenyl Cycles (BBBCs)			
	 Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) 			
	Polychlorinated Bipnenyl (PCB) Polychlorinated Terphenyls (PCT)			
	Polyvinyl Chloride (PVC) — except for wires and cables, and certain retail packaging has been			
	voluntarily removed from most applications.			
	Radioactive Substances			
	• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)			
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:			
	Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging			
	materials.			
	Eliminate the use of ozone-depleting substances (ODS) in packaging materials.			
	Design packaging materials for ease of disassembly.			
	Maximize the use of post-consumer recycled content materials in packaging materials.			
	Use readily recyclable packaging materials such as paper and corrugated materials. Padves size and weight of packages to improve transportation final officiency.			
	 Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. 			
	riastic packaging materials are marked according to 150 + 1469 and DIN 6120 Standards.			

Standard Features and Configurable Components (availability may vary by country)

End-of-life Management and Recycling

HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_ Certificate.pdf

and

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

SERVICE AND SUPPORT

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.¹⁸

- 15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
- 16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
- 17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
- 18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Standard Features and Configurable Components (availability may vary by country)

GRAPHICS

AMD® Radeon™ RX550 4GB FH PCIe x16

Engine Clock 1183MHz

Memory Clock 7 Gbps

Memory Size(width) 4 GB(128-bit)

Memory Type GDDR5

 Max. Resolution(HDMI)
 4096x2160 @ 60Hz

 Max. Resolution(DP)
 5120x2880 @ 60Hz

Multi Display Support 3 displays

HDCP Compliance Yes

Rear I/O connectors(bracket) HDMI, DPx2

Cooling(active/passive) Active fan-sink(Active cooling with dynamic speed)

Total power consumption(W) <62W

PCB form-factor with bracket ATX (Full height) PCB with ATX single slot bracket

AMD® Radeon™ RX580 4GB FH PCIe x16

Engine Clock 1266 MHz **Memory Clock** 8gbs

 Memory Size(width)
 4 GB(256-bit)

 Memory Type
 128M x 32 GDDR5

 Max. Resolution(HDMI)
 4096x2160@60Hz

 Max. Resolution(DP)
 5120x3200@60Hz

Multi Display Support 4 displays

HDCP Compliance Yes

Rear I/O connectors(bracket) DP*3 + HDMI

Cooling(active/passive) Active fan-sink (Active cooling with dynamic speed)

Total power consumption(W) <150W

PCB form-factor with bracket ATX (Full height) PCB with ATX dual slot bracket

AMD® Radeon™ R7 430 2GB VGA+DP Graphics Card

Engine Clock 780 MHz

Memory Clock 1100 MHz

Memory Size(width) 2 GB(128-bit)

Memory Type 128M x 32 GDDR5

Max. Resolution(VGA) 2048x1536

Max. Resolution(DP) 4096x2160@60Hz

Multi Display Support 2 displays HDCP Compliance yes
Rear I/O connectors(bracket) VGA+DP

Cooling(active/passive) Active fan-sink(Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket



Standard Features and Configurable Components (availability may vary by country)

AMD® Radeon™ R7 430 2GB VGA+DP Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)2GB(128-bit)Memory Type128M x 32 GDDR5Max. Resolution(VGA)2048x1536

Max. Resolution(DP) 4096x2160@60Hz

Multi Display Support 2 displays
HDCP Compliance yes
Rear I/O connectors(bracket) VGA+DP

Cooling(active/passive) Active fan-sink(Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket

AMD® Radeon™ R7 430 2GB 2DP Graphics Card

Engine Clock780 MHzMemory Clock1100 MHzMemory Size(width)2 GB(128-bit)Memory Type128M x 32 GDDR5Max. Resolution(DP)4096x2160@60Hz

Multi Display Support 2 displays

HDCP Compliance yes
Rear I/O connectors(bracket) 2DP

Cooling(active/passive) Active fan-sink(Active cooling with dynamic speed)

Total power consumption(W) <50W

PCB form-factor with bracket LP PCB with FH/LP bracket



Standard Features and Configurable Components (availability may vary by country)

STORAGE

HP 500 GB 7.2K SATA 6.0Gb/s 2.5" Hard Disk Drive

Capacity500 GBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size16 MB

Logical Blocks 976,773,168 **Seek Time** 12 ms (Average)

 Height
 0.267 in/6.8 mm (nominal)

 Width
 2.75 in/70 mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP 1 TB 7.2K SATA 6.0Gb/s 2.5" Hard Disk Drive

Capacity1 TBRotational Speed7,200 rpmInterfaceSATA 6 Gb/sBuffer Size32 MB

Logical Blocks 1,953,525,168
Seek Time 12 ms (Average)

 Height
 0.374 in/9.5 mm (nominal)

 Width
 2.75 in/70 mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Standard Features and Configurable Components (availability may vary by country)

HP 500 GB SATA 6G 2.5" 8GB Solid State Hybrid Drive (SSHD)

Capacity 500 GB
Rotational Speed 5,400 rpm

Drive Type Solid State Hybrid Drive (SSHD) technology with NAND Flash

InterfaceSATA 6 Gb/sBuffer Size64 MBNAND Flash8 GB

Seek Time 12 ms (Average)

 Height
 0.267 in/6.8 mm (nominal)

 Width
 2.75 in/70 mm (nominal)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP 1 TB SATA 6G 2.5" 8GB Solid State Hybrid Drive (SSHD)

Capacity 1 TB

Rotational Speed 5,400 rpm

Drive Type Solid State Hybrid Drive (SSHD) technology with NAND Flash

InterfaceSATA 6 Gb/sBuffer Size64 MBNAND Flash8 GB

Seek Time 12 ms (Average)

 Height
 0.374 in/9.5 mm (nominal)

 Width
 2.75 in/70 mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP 2 TB SATA 6G 2.5" 8 GB Solid State Hybrid Drive (SSHD)

Capacity 2 TB
Rotational Speed 5,400 rpm

Drive Type Solid State Hybrid Drive (SSHD) technology with NAND Flash

Interface SATA 6 Gb/s
Buffer Size 128 MB
NAND Flash 8 GB

Seek Time 12 ms (Average)

 Height
 0.374 in/9.5 mm (nominal)

 Width
 2.75 in/70 mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Standard Features and Configurable Components (availability may vary by country)

HP 2 TB 5.4K SATA 6.0Gb/s 2.5" Hard Disk Drive

Capacity2 TBRotational Speed5,400 rpmInterfaceSATA 6 Gb/sBuffer Size128 MB

Logical Blocks 3,907,050,336 **Seek Time** 12 ms (Average)

 Height
 0.374 in/9.5 mm (nominal)

 Width
 2.75 in/70 mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500 GB 2.5" FIPS 140-2 SED Solid State Drive

Capacity 500 GB

Architecture Self-Encrypting (SED) Solid State Drive with SATA interface

InterfaceSATA 6 Gb/sBuffer Size32 MB

Logical Blocks 976,773,168 **Seek Time** 12 ms (Average)

 Height
 0.267 in/6.8 mm (nominal)

 Width
 2.75 in/70 mm (nominal)

 Operating Temperature
 41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



Standard Features and Configurable Components (availability may vary by country)

NETWORKING AND COMMUNICATIONS

HP EliteDesk 705 G4 Microtower

Realtek RTL8111EPH 10/100/1000 Integrated NIC	
Connector	RJ-45
System Interface	PCIe + SMBus
Controller	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
	100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
	1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)
	Auto-Negotiation (Automatic Speed Selection)
	Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
Data rates supported	IEEE 802.1p QoS (Quality of Service) Support
	IEEE 802.1q VLAN support
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)
	IEEE 802.3az EEE (Energy Efficient Ethernet)
IEEE Compliance	TCP/IP/UDP Checksum Offload (configurable)
	Protocol Offload (ARP & NS)
	Large send offload and Giant send offload
	Receiving Side Scaling
	Jumbo Frame 9K
Performance	Cable Disconnetion: 25mW
	100Mbps Full Run: 450mW
	1000bp Full Run: 1000mW
	WoL Enable(S3/S4/S5): 50mW
	WoL Disable(S3/S4/S5): 25mW
Power	ACPI compliant – multiple power modes
	Situation-sensitive features reduce power consumption
	Advanced link down power saving for reducing link down power consumption
MAC/PHY Interconnect	Auto MDI/MDIX Crossover cable detection
Management Interface	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame);
	Wake-on-LAN from off (Magic Packet only)
	PXE 2.1 Remote Boot
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))
	Comprehensive diagnostic and configuration software suite
	Virtual Cable Doctor for Ethernet cable status

Intel® Ethernet I210-T1 Gigabit Network Adapter	
Connector	RJ-45
System Interface	PCIe Express x1
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
	100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
	1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)
	Auto-Negotiation (Automatic Speed Selection)
	Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support
	IEEE 802.1q VLAN support
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)
	IEEE 802.3az EEE (Energy Efficient Ethernet)
Performance	TCP/IP/UDP Checksum Offload (configurable)
	Protocol Offload (ARP & NS)
	Large send offload and Giant send offload
	Receiving Side Scaling
	Jumbo Frame 9K



Power consumption	Cable Disconnection: 25mW
	100Mbps Full Run: 450mW
	1000bp Full Run: 1000mW
	WoL Enable(S3/S4/S5): 50mW
	WoL Disable(S3/S4/S5): 25mW
Power	ACPI compliant – multiple power modes
Management	Situation-sensitive features reduce power consumption
	Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame);
	Wake-on-LAN from off (Magic Packet only)
	PXE 2.1 Remote Boot
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))
	Comprehensive diagnostic and configuration software suite
	Virtual Cable Doctor for Ethernet cable status

Intel Thunder Peak 9260 802.11a/b/g/n/ac (2x2) WiFi and Bluetooth® 5.0 Combo¹ Non-vPro		
Wireless LAN Standards	IEEE 802.11a	
	IEEE 802.11b	
	IEEE 802.11g	
	IEEE 802.11n	
	IEEE 802.11ac	
Interoperability	Wi-Fi certified	
Frequency Band	802.11b/g/n	
	• 2.402 – 2.482 GHz	
	802.11a/n	
	• 4.9 – 4.95 GHz (Japan)	
	• 5.15 – 5.25 GHz	
	• 5.25 – 5.35 GHz	
	• 5.47 – 5.725 GHz	
	• 5.825 – 5.850 GHz	
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps	
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)	
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)	
Modulation	Direct Sequence Spread Spectrum	
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
Security ¹	 IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only 	
	AES-CCMP: 128 bit in hardware	
	• 802.1x authentication	
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.	
	WPA2 certification	
	• IEEE 802.11i	
	Cisco Certified Extensions, all versions through CCX4 and CCX Lite	
	• WAPI	
Network Architecture	Ad-hoc (Peer to Peer)	
Models	Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power ²	• 802.11b: +18.5dBm minimum	
	• 802.11g: +17.5dBm minimum	
	• 802.11a: +18.5dBm minimum	
	• 802.11n HT20(2.4GHz): +15.5dBm minimum	



		.4GHz) : +14.5dBm minimum
	• 802.11n HT20(50	GHz) : +15.5dBm minimum
	• 802.11n HT40(50	GHz) : +14.5dBm minimum
	• 802.11ac VHT80	(5GHz) : +11.5dBm minimum
	• 802.11ac VHT16	0(5GHz): +11.5dBm minimum
Power Consumption	• Transmit mode2.0 W	
	Receive mode 1	I.6 W
	1	180 mW (WLAN Associated)
		V (WLAN unassociated)
	 Connected Stand 	
	• Radio disabled 8	
Power Management		ess compliant power management
		power saving mode
Receiver Sensitivity ³	802.11b, 1Mbps: -93.5dBm maximum	
		-84dBm maximum
		: -86dBm maximum
		s: -72dBm maximum
	802.11n, MCS07: -	
	802.11n, MCS15: -	
	802.11ac, MCS0: -8	
	802.11ac, MCS9: -	
Antenna type	High efficiency ant	tenna with spatial diversity, mounted in the display enclosure
		11 15 45 50
		al band 2.4/5 GHz antennas are provided to the card to support WLAN
		cions and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230: 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating	14° to 158° F (–10° to 70° C)
	Non-operating	-40° to 176° F (-40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	· ·	o OFF; LED White – Radio ON
1 Chack latect coftwar	aldrivar ralazca for updatac	c on cupported cocurity features

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

IP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0 Wireless Technology		
Bluetooth® Specification	4.0/4.1/4.2/5.0 Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps	
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps	
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.	



Power Consumption	Peak (Tx) 330 mW
	Peak (Rx) 230 mW
	Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth® Software Supported	Microsoft Windows Bluetooth® Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance
	LE Link Layer Ping
	LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising
	LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 –Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)

Realtek 802.11a/b/g/n/ac (2x	2.11a/b/g/n/ac (2x2) WiFi and Bluetooth® 4.2 Combo¹	
Wireless LAN Standards	IEEE 802.11a	
	IEEE 802.11b	
	IEEE 802.11g	
	IEEE 802.11n	
	IEEE 802.11ac	
Interoperability	Wi-Fi certified	
Frequency Band	802.11b/g/n	
	• 2.402 – 2.482 GHz	
	802.11a/n	
	• 4.9 – 4.95 GHz (Japan)	
	• 5.15 – 5.25 GHz	
	• 5.25 – 5.35 GHz	
	• 5.47 – 5.725 GHz	
	• 5.825 – 5.850 GHz	
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps	
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)	
	• 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)	
Modulation	Direct Sequence Spread Spectrum	
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
Security ³	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only	
	AES-CCMP: 128 bit in hardware	
	• 802.1x authentication	
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.	



	WPA2 certification	
	• IEEE 802.11i	
	Cisco Certified Extensions, all versions through CCX4 and CCX Lite	
	• WAPI	
Network Architecture	Ad-hoc (Peer to Peer)	
Models	Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power ²	• 802.11b: +14dBm minimum	
	• 802.11g: +12dBm minimum	
	• 802.11a: +12dBm minimum	
	• 802.11n HT20(2.4GHz): +12dBm minimum	
	• 802.11n HT40(2.4GHz): +12dBm minimum	
	• 802.11n HT20(5GHz): +10dBm minimum	
	• 802.11n HT40(5GHz): +10dBm minimum	
	802.11ac VHT80(5GHz): +10dBm minimum	
Power Consumption	• Transmit mode2.0 W	
	• Receive mode 1.6 W	
	• Idle mode (PSP) 180 mW (WLAN Associated)	
	• Idle mode 50 mW (WLAN unassociated)	
	Connected Standby 10mW Radio disabled 8 mW	
Power Management	ACPI and PCI Express compliant power management	
rowei Management	802.11 compliant power saving mode	
Receiver Sensitivity ³	802.11b, 1Mbps: -93.5dBm maximum	
Receiver Sensitivity	802.11b, 11Mbps: -84dBm maximum	
	802.11a/g, 6Mbps: -86dBm maximum	
	802.11a/g, 54Mbps: -72dBm maximum	
	802.11n, MCS07: -67dBm maximum	
	802.11n, MCS15: -64dBm maximum	
	802.11ac, MCS0: -84dBm maximum	
	802.11ac, MCS9: -59dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure	
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN	
	MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230 : 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating 14° to 158° F (–10° to 70° C)	
	Non-operating –40° to 176° F (–40° to 80° C)	
Humidity	Operating 10% to 90% (non-condensing)	
	Non-operating 5% to 95% (non-condensing)	
Altitude	Operating 0 to 10,000 ft (3,048 m)	
	Non-operating 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF; LED White – Radio ON	
1. Check latest software	l/driver release for updates on supported security features.	

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology	
Bluetooth® Specification 4.0/4.1/4.2 Compliant	
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)



	BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
	Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Fransmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
lectrical Interface	USB 2.0 compliant
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Power Management Certifications	ETS 300 328, ETS 300 826
	Low Voltage Directive IEC950
	UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping
	LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 –Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP) Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)



Standard Features and Configurable Components (availability may vary by country)

HP EliteDesk 705 G4 Small Form Factor Business PC

Realtek RTL8111EPH 10/100/1000 Integrated NIC	
Connector	RJ-45
System Interface	PCIe + SMBus
Controller	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
Data rates supported	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
IEEE Compliance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
Performance	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
MAC/PHY Interconnect	Auto MDI/MDIX Crossover cable detection
Management Interface	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)



Intel® Ethernet I210-T1 Gigal	bit Network Adapter	
Connector	RJ-45	
System Interface	PCI (Intel® proprietary) + SMBus	
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)	
	100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)	
	1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)	
	Auto-Negotiation (Automatic Speed Selection)	
	Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s	
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support	
	IEEE 802.1q VLAN support	
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)	
	IEEE 802.3az EEE (Energy Efficient Ethernet)	
Performance	TCP/IP/UDP Checksum Offload (configurable)	
	Protocol Offload (ARP & NS)	
	Large send offload and Giant send offload	
	Receiving Side Scaling	
	Jumbo Frame 9K	
Power consumption	Cable Disconnection: 25mW	
	100Mbps Full Run: 450mW	
	1000bp Full Run: 1000mW	
	WoL Enable(S3/S4/S5): 50mW	
	WoL Disable(S3/S4/S5): 25mW	
Power	ACPI compliant – multiple power modes	
Management	Situation-sensitive features reduce power consumption	
	Advanced link down power saving for reducing link down power consumption	
Management Interface	Auto MDI/MDIX Crossover cable detection	
IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame);	
	Wake-on-LAN from off (Magic Packet only)	
	PXE 2.1 Remote Boot	
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))	
	Comprehensive diagnostic and configuration software suite	
	Virtual Cable Doctor for Ethernet cable status	
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components	



Intel® Thunder Peak 9260 802	.11a/b/g/n/ac (2x2) WiFi and Bluetooth® 5.0 Combo¹ Non-vPro	
Wireless LAN Standards	IEEE 802.11a	
	IEEE 802.11b	
	IEEE 802.11g	
	IEEE 802.11n	
	IEEE 802.11ac	
Interoperability	Wi-Fi certified	
Frequency Band	802.11b/g/n	
	• 2.402 – 2.482 GHz	
	802.11a/n	
	• 4.9 – 4.95 GHz (Japan)	
	• 5.15 – 5.25 GHz	
	• 5.25 – 5.35 GHz	
	• 5.47 – 5.725 GHz	
	• 5.825 – 5.850 GHz	
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps	
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)	
	• 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)	
Modulation	Direct Sequence Spread Spectrum	
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
Security ¹	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only	
	AES-CCMP: 128 bit in hardware	
	• 802.1x authentication	
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.	
	WPA2 certification	
	• IEEE 802.11i	
	Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI	
Network Architecture	Ad-hoc (Peer to Peer)	
Models	Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power ²	• 802.11b: +18.5dBm minimum	
output i owei	• 802.11g : +17.5dBm minimum	
	• 802.11a : +18.5dBm minimum	
	• 802.11n HT20(2.4GHz): +15.5dBm minimum	
	• 802.11n HT40(2.4GHz): +14.5dBm minimum	
	• 802.11n HT20(5GHz) : +15.5dBm minimum	
	• 802.11n HT40(5GHz) : +14.5dBm minimum	
	• 802.11ac VHT80(5GHz): +11.5dBm minimum	
	• 802.11ac VHT160(5GHz): +11.5dBm minimum	
Power Consumption	• Transmit mode2.0 W	
-	Receive mode 1.6 W	
	• Idle mode (PSP) 180 mW (WLAN Associated)	
	• Idle mode 50 mW (WLAN unassociated)	
	Connected Standby 10mW	
	Radio disabled 8 mW	
Power Management	ACPI and PCI Express compliant power management	
	802.11 compliant power saving mode	
Receiver Sensitivity ³	802.11b, 1Mbps : -93.5dBm maximum	
	802.11b, 11Mbps : -84dBm maximum	



		s : -86dBm maximum	
	802.11a/g, 54Mbp	os : -72dBm maximum	
	802.11n, MCS07:	802.11n, MCS07 : -67dBm maximum	
	802.11n, MCS15:	-64dBm maximum	
	802.11ac, MCS0 : -	-84dBm maximum	
	802.11ac, MCS9 : -	-59dBm maximum	
Antenna type	High efficiency and	tenna with spatial diversity, mounted in the display enclosure	
	Two embedded du	ual band 2.4/5 GHz antennas are provided to the card to support WLAN	
	MIMO communicat	MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 M	PCI-Express M.2 MiniCard	
Dimensions	Type 2230 : 2.3 x 2	Type 2230 : 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230 : 2.8g	Type 2230 : 2.8g	
Operating Voltage	3.3v +/- 9%		
Temperature	Operating	14° to 158° F (–10° to 70° C)	
	Non-operating	-40° to 176° F (-40° to 80° C)	
Humidity	Operating	10% to 90% (non-condensing)	
-	Non-operating	5% to 95% (non-condensing)	
Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF; LED White – Radio ON		
1 Check latest softwar	oldriver release for undate	s on supported security features	

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

10% for 802.11a/g (OFDM modulation).		
HP Integrated Module with Bluetoot	h 4.0/4.1/4.2/5.0 Wireless Technology	
Bluetooth® Specification	4.0/4.1/4.2/5.0 Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps	
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps	
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW	
Electrical Interface	USB 2.0 compliant	
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark	
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising	



Standard Features and Configurable Components (availability may vary by country)

LE L2CAP Connection Oriented Channels
Train Nudging & Interlaced Scan
BT4.2 ESR08 Compliance
LE Secure Connection- Basic/Full
LE Privacy 1.2 –Link Layer Privacy
LE Privacy 1.2 –Extended Scanner Filter Policies
LE Data Packet Length Extension
FAX Profile (FAX)
Basic Imaging Profile (BIP)2
Headset Profile (HSP)
Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP)



Ia/b/g/n/ac (1x1) WiFi and Bluetooth® 4.2 Combo¹	
IEEE 802.11a	
IEEE 802.11b	
IEEE 802.11g	
IEEE 802.11n	
IEEE 802.11ac	
Wi-Fi certified	
802.11b/g/n	
• 2.402 – 2.482 GHz	
802.11a/n	
• 4.9 – 4.95 GHz (Japan)	
• 5.15 – 5.25 GHz	
• 5.25 – 5.35 GHz	
• 5.47 – 5.725 GHz	
• 5.825 – 5.850 GHz	
• 802.11b: 1, 2, 5.5, 11 Mbps	
• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)	
• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)	
Direct Sequence Spread Spectrum	
BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only	
AES-CCMP: 128 bit in hardware	
• 802.1x authentication	
WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.	
WPA2 certification	
• IEEE 802.11i	
Cisco Certified Extensions, all versions through CCX4 and CCX Lite	
• WAPI	
Ad-hoc (Peer to Peer)	
Infrastructure (Access Point Required)	
IEEE 802.11 compliant roaming between access points	
• 802.11b : +18.5dBm minimum	
• 802.11g : +17.5dBm minimum	
• 802.11a : +18.5dBm minimum	
• 802.11n HT20(2.4GHz) : +15.5dBm minimum	
• 802.11n HT40(2.4GHz) : +14.5dBm minimum	
• 802.11n HT20(5GHz): +15.5dBm minimum	
• 802.11n HT40(5GHz) : +14.5dBm minimum	
• 802.11ac VHT80(5GHz) : +11.5dBm minimum	
• Transmit mode2.0 W	
Receive mode 1.6 W	
Idle mode (PSP) 180 mW (WLAN Associated)	
• Idle mode 50 mW (WLAN unassociated)	
Connected Standby 10mW	
• Radio disabled 8 mW	
ACPI and PCI Express compliant power management	
802.11 compliant power saving mode	
802.11b, 1Mbps : -93.5dBm maximum	
802.11b, 11Mbps : -84dBm maximum	
802.11a/g, 6Mbps : -86dBm maximum	
ooz. i ia, g, oriops . oodbiii iidaliiidiii	
802.11a/g, 54Mbps : -72dBm maximum	



	802.11n. MCS15 :	-64dBm maximum	
	802.11ac, MCS0: -84dBm maximum		
		802.11ac, MCS9 : -59dBm maximum	
Antenna type	High efficiency an	High efficiency antenna with spatial diversity, mounted in the display enclosure	
	Two embedded du	ual band 2.4/5 GHz antennas are provided to the card to support WLAN	
	MIMO communica	MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 M	PCI-Express M.2 MiniCard	
Dimensions	Type 2230 : 2.3 x	Type 2230 : 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230 : 2.8g	Type 2230 : 2.8g	
Operating Voltage	3.3v +/- 9%	3.3v +/- 9%	
Temperature	Operating	Operating 14° to 158° F (–10° to 70° C)	
	Non-operating	-40° to 176° F (-40° to 80° C)	
Humidity	Operating	Operating 10% to 90% (non-condensing)	
	Non-operating	Non-operating 5% to 95% (non-condensing)	
Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF; LED White – Radio ON		

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

for 802.11a/g (OFDM modu	lation).	
HP Integrated Module with Bluetoo	th 4.0/4.1/4.2 Wireless Technology	
Bluetooth® Specification	4.0/4.1/4.2 Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps	
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps	
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW	
Electrical Interface	USB 2.0 compliant	
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark	
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance	



LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX)
Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Wireless LAN Standards	11a/b/g/n/ac (2x2) WiFi and Bluetooth® 4.2 Combo¹ Non-vPro IEEE 802.11a	
Trii Cicoo Eriit Standaras	IEEE 802.11b	
	IEEE 802.11g	
	IEEE 802.11n	
	IEEE 802.11ac	
Interoperability	Wi-Fi certified	
Frequency Band	802.11b/g/n	
riequency band	• 2.402 – 2.482 GHz	
	802.11a/n	
	• 4.9 – 4.95 GHz (Japan)	
	• 5.15 – 5.25 GHz	
	• 5.25 – 5.35 GHz	
	• 5.47 – 5.725 GHz	
	• 5.825 – 5.850 GHz	
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps	
Data Rates	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)	
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)	
Modulation	Direct Sequence Spread Spectrum	
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
Security ³	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only	
•	AES-CCMP: 128 bit in hardware	
	• 802.1x authentication	
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.	
	WPA2 certification	
	• IEEE 802.11i	
	Cisco Certified Extensions, all versions through CCX4 and CCX Lite	
	• WAPI	
Network Architecture	Ad-hoc (Peer to Peer)	
Models	Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power ²	• 802.11b : +18.5dBm minimum	
•	• 802.11g: +17.5dBm minimum	
	• 802.11a: +18.5dBm minimum	
	• 802.11n HT20(2.4GHz): +15.5dBm minimum	
	• 802.11n HT40(2.4GHz): +14.5dBm minimum	
	• 802.11n HT20(5GHz): +15.5dBm minimum	
	• 802.11n HT40(5GHz): +14.5dBm minimum	
	• 802.11ac VHT80(5GHz) : +11.5dBm minimum	
Power Consumption	• Transmit mode2.0 W	
-	• Receive mode 1.6 W	
	• Idle mode (PSP) 180 mW (WLAN Associated)	



	a Idla mada FO mi	N/WI AN upaccociated	
	10.00	Idle mode 50 mW (WLAN unassociated) Connected Standby 10mW	
		Connected Standby 10mW Padio disabled 8 mW	
		Radio disabled 8 mW	
Power Management	-	ACPI and PCI Express compliant power management	
		power saving mode	
Receiver Sensitivity ³		-93.5dBm maximum	
	802.11b, 11Mbps	: -84dBm maximum	
	802.11a/g, 6Mbps	s : -86dBm maximum	
	802.11a/g, 54Mbp	os : -72dBm maximum	
	802.11n, MCS07:	-67dBm maximum	
	802.11n, MCS15:	-64dBm maximum	
	802.11ac, MCS0 :	-84dBm maximum	
	802.11ac, MCS9 :	802.11ac, MCS9 : -59dBm maximum	
Antenna type	High efficiency an	High efficiency antenna with spatial diversity, mounted in the display enclosure	
	Two embedded du	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN	
	MIMO communicat	MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 M	PCI-Express M.2 MiniCard	
Dimensions	Type 2230 : 2.3 x i	Type 2230 : 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230 : 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating	14° to 158° F (–10° to 70° C)	
•	Non-operating	-40° to 176° F (-40° to 80° C)	
Humidity	Operating	·	
-	Non-operating		
Altitude	Operating	·	
	Non-operating	0 to 50,000 ft (15,240 m)	
LED Activity		o OFF; LED White – Radio ON	
		c on cupported cocurity foatures	

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

101 002:114/9 (01 21 111104)	atation):	
HP Integrated Module with Bluetoo	th 4.0/4.1/4.2 Wireless Technology	
Bluetooth® Specification	4.0/4.1/4.2 Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps	
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps	
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW	
Electrical Interface	USB 2.0 compliant	
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Power Management Certifications		



	ETC 200 220 ETC 200 026
	ETS 300 328, ETS 300 826
	Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance
	LE Link Layer Ping
	LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising
	LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 –Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)

Realtek 802.11a/b/g/n/ac (1)	x1) WiFi and Bluetooth® 4.2 Combo¹	
Wireless LAN Standards	IEEE 802.11a	
	IEEE 802.11b	
	IEEE 802.11g	
	IEEE 802.11n	
	IEEE 802.11ac	
Interoperability	Wi-Fi certified	
Frequency Band	802.11b/g/n	
	• 2.402 – 2.482 GHz	
	802.11a/n	
	• 4.9 – 4.95 GHz (Japan)	
	• 5.15 – 5.25 GHz	
	• 5.25 – 5.35 GHz	
	• 5.47 – 5.725 GHz	
	• 5.825 – 5.850 GHz	
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps	
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)	
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)	
Modulation	Direct Sequence Spread Spectrum	
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
Security ¹	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only	
	AES-CCMP: 128 bit in hardware	
	• 802.1x authentication	
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.	
	WPA2 certification	
	• IEEE 802.11i	
	Cisco Certified Extensions, all versions through CCX4 and CCX Lite	
	• WAPI	
Network Architecture	Ad-hoc (Peer to Peer)	
Models	Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power ²	• 802.11b : +14dBm minimum	
	• 802.11g: +12dBm minimum	



	• 802.11a : +12dBm minimum		
	• 802.11n HT20(2.4GHz): +12dBm minimum		
	• 802.11n HT40(2.4GHz) : +12dBm minimum		
	• 802.11n HT20(5GHz): +10dBm minimum		
	• 802.11n HT40(5GHz): +10dBm minimum		
	• 802.11ac VHT80(5GHz) : +10dBm minimum		
Power Consumption	Transmit mode2.0 W		
	Receive mode 1.6 W		
	 Idle mode (PSP) 180 mW (WLAN Associated) 		
	 Idle mode 50 mW (WLAN unassociated) 		
	Connected Standby 10mW		
	Radio disabled 8 mW		
Power Management	ACPI and PCI Express compliant power management		
	802.11 compliant power saving mode		
Receiver Sensitivity ³	802.11b, 1Mbps : -93.5dBm maximum		
	802.11b, 11Mbps : -84dBm maximum		
	802.11a/g, 6Mbps : -86dBm maximum		
	802.11a/g, 54Mbps : -72dBm maximum		
	802.11n, MCS07 : -67dBm maximum		
	802.11n, MCS15 : -64dBm maximum		
	802.11ac, MCS0 : -84dBm maximum		
	802.11ac, MCS9 : -59dBm maximum		
Antenna type	High efficiency antenna.		
	One embedded dual band 2.4/5 GHz antenna is provide	d to the card to support WLAN	
	communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm		
Weight	Type 2230 : 2.8g	Type 2230 : 2.8g	
Operating Voltage	3.3v +/- 9%		
Temperature	Operating 14° to 158° F (–10° to 70° C)		
	Non-operating -40° to 176° F (-40° to 80° C)		
Humidity	Operating 10% to 90% (non-condensing)		
	Non-operating 5% to 95% (non-condensing)		
Altitude	Operating 0 to 10,000 ft (3,048 m)		
	Non-operating 0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Radio OFF; LED White – Radio ON		
1 Chock latest coftware	driver release for undates on supported security features		

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

IP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology	
Bluetooth® Specification	4.0/4.1/4.2 Compliant
Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.



Power Consumption	Peak (Tx) 330 mW	
	Peak (Rx) 230 mW	
	Selective Suspend 17 mW	
Electrical Interface	USB 2.0 compliant	
Bluetooth® Software Supported	Microsoft Windows Bluetooth® Software	
Link Topology		
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Power Management Certifications	ETS 300 328, ETS 300 826	
_	Low Voltage Directive IEC950 UL, CSA, and CE Mark	
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance	
	LE Link Layer Ping	
	LE Dual Mode	
	LE Link Layer	
	LE Low Duty Cycle Directed Advertising	
	LE L2CAP Connection Oriented Channels	
	Train Nudging & Interlaced Scan	
	BT4.2 ESR08 Compliance	
	LE Secure Connection- Basic/Full	
	LE Privacy 1.2 –Link Layer Privacy	
	LE Privacy 1.2 –Extended Scanner Filter Policies	
	LE Data Packet Length Extension	
	FAX Profile (FAX)	
	Basic Imaging Profile (BIP)2	
	Headset Profile (HSP)	
	Hands Free Profile (HFP)	
	Advanced Audio Distribution Profile (A2DP)	

	.11a/b/g/n/ac (2x2) WiFi and Bluetooth® 5.0 Combo¹ Non-vPro
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n
	• 2.402 – 2.482 GHz
	802.11a/n
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ¹	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
-	AES-CCMP: 128 bit in hardware



	002.4		
	• 802.1x authentic		
		.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.	
	WPA2 certification	on	
	• IEEE 802.11i		
	Cisco Certified Ex	tensions, all versions through CCX4 and CCX Lite	
	• WAPI		
Network Architecture	Ad-hoc (Peer to Pe	Ad-hoc (Peer to Peer)	
Models	Infrastructure (Acc	ess Point Required)	
Roaming	IEEE 802.11 comp	liant roaming between access points	
Output Power ²	• 802.11b : +18.5d	Bm minimum	
•	• 802.11g: +17.5d	Bm minimum	
	• 802.11a : +18.5d		
		4GHz): +15.5dBm minimum	
		4GHz): +14.5dBm minimum	
	_	GHz): +15.5dBm minimum	
	_	GHz): +14.5dBm minimum	
		(5GHz): +11.5dBm minimum	
		0(5GHz): +11.5dBm minimum	
Power Consumption	Transmit mode2		
rower consumption	• Receive mode		
		180 mW (WLAN Associated)	
		/ (WLAN unassociated)	
	Connected Standby 10mW Padia disabled 8 and 9		
	Radio disabled 8		
Power Management		ess compliant power management	
		power saving mode	
Receiver Sensitivity ³	802.11b, 1Mbps : -93.5dBm maximum		
		-84dBm maximum	
		: -86dBm maximum	
		s : -72dBm maximum	
		-67dBm maximum	
	802.11n, MCS15:		
	802.11ac, MCS0 : -		
	802.11ac, MCS9 : -		
Antenna type	High efficiency ant	enna with spatial diversity, mounted in the display enclosure	
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN		
	MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 M		
	·		
Dimensions		Type 2230 : 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230 : 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating	14° to 158° F (-10° to 70° C)	
	Non-operating	-40° to 176° F (-40° to 80° C)	
Humidity	Operating	10% to 90% (non-condensing)	
	Non-operating	5% to 95% (non-condensing)	
Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
LED Activity		OFF; LED White – Radio ON	
	· · · · · · · · · · · · · · · · · · ·	s on supported security features.	

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/q (OFDM modulation).

,	
HP Integrated Module with Bluetootl	n 4.0/4.1/4.2/5.0 Wireless Technology
Rluetooth® Specification	4 0/4 1/4 2/5 0 Compliant



Frequency Band	2402 to 2480 MHz
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW
	Peak (Rx) 230 mW
	Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance
	LE Link Layer Ping
	LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising
	LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 –Link Layer Privacy
	LE Privacy 1.2 –Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)



Standard Features and Configurable Components (availability may vary by country)

HP EliteDesk 705 G4 Desktop Mini Business PC

Intel® Sandy Peak 3168 802.1	1a/b/g/n/ac (1x1) WiFi and Bluetooth® 4.2 Combo [1]
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n
	• 2.402 – 2.482 GHz
	802.11a/n
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ³	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
-	AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	• IEEE 802.11i
	 Cisco Certified Extensions, all versions through CCX4 and CCX Lite
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ²	• 802.11b : +18.5dBm minimum
	• 802.11g : +17.5dBm minimum
	• 802.11a : +18.5dBm minimum
	• 802.11n HT20(2.4GHz): +15.5dBm minimum
	• 802.11n HT40(2.4GHz): +14.5dBm minimum
	• 802.11n HT20(5GHz): +15.5dBm minimum
	• 802.11n HT40(5GHz): +14.5dBm minimum
	• 802.11ac VHT80(5GHz) : +11.5dBm minimum
Power Consumption	• Transmit mode2.0 W
	Receive mode 1.6 W
	• Idle mode (PSP) 180 mW (WLAN Associated)
	• Idle mode 50 mW (WLAN unassociated)
	Connected Standby 10mW
	• Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management
	802.11 compliant power saving mode
Receiver Sensitivity ³	802.11b, 1Mbps : -93.5dBm maximum
	802.11b, 11Mbps : -84dBm maximum
	802.11a/g, 6Mbps : -86dBm maximum
	802.11a/g, 54Mbps : -72dBm maximum
	802.11n, MCS07 : -67dBm maximum



	802.11n. MCS15 :	-64dBm maximum	
	-	802.11ac, MCS0 : -84dBm maximum	
		-59dBm maximum	
Antenna type	High efficiency an	tenna with spatial diversity, mounted in the display enclosure	
	Two embedded du	ual band 2.4/5 GHz antennas are provided to the card to support WLAN	
	MIMO communica	tions and Bluetooth communications	
Form Factor	PCI-Express M.2 M	1iniCard	
Dimensions	Type 2230 : 2.3 x	22.0 x 30.0 mm	
Weight	Type 2230 : 2.8g		
Operating Voltage	3.3v +/- 9%	3.3v +/- 9%	
Temperature	Operating	14° to 158° F (–10° to 70° C)	
	Non-operating	-40° to 176° F (-40° to 80° C)	
Humidity	Operating	10% to 90% (non-condensing)	
	Non-operating	5% to 95% (non-condensing)	
Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radi	o OFF; LED White – Radio ON	

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

for 802.11a/g (OFDM modu	lation).	
HP Integrated Module with Bluetoo	th 4.0/4.1/4.2 Wireless Technology	
Bluetooth® Specification	4.0/4.1/4.2 Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps	
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps	
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW	
Electrical Interface	USB 2.0 compliant	
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark	
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance	



LE Secure Connection- Basic/Full
LE Privacy 1.2 –Link Layer Privacy
LE Privacy 1.2 –Extended Scanner Filter Policies
LE Data Packet Length Extension
FAX Profile (FAX)
Basic Imaging Profile (BIP)2
Headset Profile (HSP)
Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP)

Intel® Ethernet I210-T1 Gigal	Intel® Ethernet I210-T1 Gigabit Network Adapter	
Connector	RJ-45	
System Interface	PCI (Intel® proprietary) + SMBus	
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)	
	100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)	
	1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)	
	Auto-Negotiation (Automatic Speed Selection)	
	Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s	
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support	
	IEEE 802.1q VLAN support	
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)	
	IEEE 802.3az EEE (Energy Efficient Ethernet)	
Performance	TCP/IP/UDP Checksum Offload (configurable)	
	Protocol Offload (ARP & NS)	
	Large send offload and Giant send offload	
	Receiving Side Scaling	
	Jumbo Frame 9K	
Power consumption	Cable Disconnetion: 25mW	
	100Mbps Full Run: 450mW	
	1000bp Full Run: 1000mW	
	WoL Enable(S3/S4/S5): 50mW	
	WoL Disable(S3/S4/S5): 25mW	
Power	ACPI compliant – multiple power modes	
Management	Situation-sensitive features reduce power consumption	
	Advanced link down power saving for reducing link down power consumption	
Management Interface	Auto MDI/MDIX Crossover cable detection	
IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame);	
	Wake-on-LAN from off (Magic Packet only)	
	PXE 2.1 Remote Boot	
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))	
	Comprehensive diagnostic and configuration software suite	
	Virtual Cable Doctor for Ethernet cable status	
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components	



Intel® Thunder Peak 9260 802	.11a/b/g/n/ac (2x2) WiFi and Bluetooth® 5.0 Combo¹ Non-vPro
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n
	• 2.402 – 2.482 GHz
	802.11a/n
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ¹	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
	AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	• IEEE 802.11i
	Cisco Certified Extensions, all versions through CCX4 and CCX Lite
Nicker and Amelika skews	• WAPI
Network Architecture Models	Ad-hoc (Peer to Peer)
Roaming	Infrastructure (Access Point Required) IEEE 802.11 compliant roaming between access points
Output Power ²	802.11b:+18.5dBm minimum
output Power-	• 802.11g : +17.5dBm minimum
	• 802.11a : +18.5dBm minimum
	• 802.11n HT20(2.4GHz): +15.5dBm minimum
	• 802.11n HT40(2.4GHz): +14.5dBm minimum
	• 802.11n HT20(5GHz) : +15.5dBm minimum
	• 802.11n HT40(5GHz) : +14.5dBm minimum
	• 802.11ac VHT80(5GHz) : +11.5dBm minimum
	• 802.11ac VHT160(5GHz) : +11.5dBm minimum
Power Consumption	• Transmit mode2.0 W
	• Receive mode 1.6 W
	• Idle mode (PSP) 180 mW (WLAN Associated)
	• Idle mode 50 mW (WLAN unassociated)
	Connected Standby 10mW
	Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management
	802.11 compliant power saving mode
Receiver Sensitivity ³	802.11b, 1Mbps : -93.5dBm maximum
	802.11b, 11Mbps : -84dBm maximum



		s : -86dBm maximum	
	802.11a/g, 54Mbp	os : -72dBm maximum	
	802.11n, MCS07 :	802.11n, MCS07 : -67dBm maximum	
	802.11n, MCS15:	-64dBm maximum	
	802.11ac, MCS0 : -	-84dBm maximum	
	802.11ac, MCS9 : -	-59dBm maximum	
Antenna type	High efficiency and	High efficiency antenna with spatial diversity, mounted in the display enclosure	
	Two embedded du	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN	
	MIMO communicat	tions and Bluetooth communications	
Form Factor	PCI-Express M.2 M	liniCard	
Dimensions	Type 2230: 2.3 x 2	Type 2230: 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230: 2.8g	Type 2230: 2.8g	
Operating Voltage	3.3v +/- 9%		
Temperature	Operating	14° to 158° F (–10° to 70° C)	
	Non-operating	-40° to 176° F (-40° to 80° C)	
Humidity	Operating	10% to 90% (non-condensing)	
-	Non-operating	5% to 95% (non-condensing)	
Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio	o OFF; LED White – Radio ON	
1 Check latest softwar	ro/driver release for undate	s on supported security features	

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

th 4.0/4.1/4.2/5.0 Wireless Technology
4.0/4.1/4.2/5.0 Compliant
2402 to 2480 MHz
Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)
Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps
BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.
Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
USB 2.0 compliant
Microsoft Windows Bluetooth® Software
Microsoft Windows ACPI, and USB Bus Support
FCC (47 CFR) Part 15C, Section 15.247 & 15.249
ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising



LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP) 2
FAX Profile (FAX)
Basic Imaging Profile (BIP)2 Headset Profile (HSP)
Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

	11a/b/g/n/ac (2x2) WiFi and Bluetooth® 4.2 Combo [1] Non-vPro
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n
	• 2.402 – 2.482 GHz
	802.11a/n
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ³	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
	AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	• IEEE 802.11i
	Cisco Certified Extensions, all versions through CCX4 and CCX Lite
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power ²	• 802.11b: +18.5dBm minimum
	• 802.11g: +17.5dBm minimum
	• 802.11a: +18.5dBm minimum
	• 802.11n HT20(2.4GHz): +15.5dBm minimum
	• 802.11n HT40(2.4GHz): +14.5dBm minimum
	• 802.11n HT20(5GHz): +15.5dBm minimum
	• 802.11n HT40(5GHz): +14.5dBm minimum
	• 802.11ac VHT80(5GHz): +11.5dBm minimum
Power Consumption	Transmit mode2.0 W



	• Receive mode 1.6 W		
	• Idle mode (PSP) 180 mW (WLAN Associated)		
	• Idle mode 50 mW (WLAN unassociated)		
	Connected Standby 10mW		
	• Radio disabled 8 mW		
Power Management	ACPI and PCI Express compliant power management		
	802.11 compliant power saving mode		
Receiver Sensitivity ³	802.11b, 1Mbps : -93.5dBm maximum		
	802.11b, 11Mbps: -84dBm maximum		
	802.11a/g, 6Mbps : -86dBm maximum		
	802.11a/g, 54Mbps : -72dBm maximum		
	802.11n, MCS07 : -67dBm maximum		
	802.11n, MCS15: -64dBm maximum		
	802.11ac, MCS0 : -84dBm maximum		
	802.11ac, MCS9 : -59dBm maximum		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure		
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN		
	MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm		
Weight	Type 2230: 2.8g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating 14° to 158° F (–10° to 70° C)		
-	Non-operating -40° to 176° F (-40° to 80° C)		
Humidity	Operating 10% to 90% (non-condensing)		
	Non-operating 5% to 95% (non-condensing)		
Altitude	Operating 0 to 10,000 ft (3,048 m)		
	Non-operating 0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Radio OFF; LED White – Radio ON		
1 Charle laterateraftering	Advisor release for undates on supported cognitive features		

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology		
Bluetooth® Specification	4.0/4.1/4.2 Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy: 3 Mbps data rate; throughput up to 2.17 Mbps	
	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps	
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW	
Electrical Interface	USB 2.0 compliant	
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support	



Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Intel® Sandy Peak 3168 802.1	1a/b/g/n/ac (1x1) WiFi and Bluetooth® 4.2 Combo¹
Wireless LAN Standards	IEEE 802.11a
	IEEE 802.11b
	IEEE 802.11g
	IEEE 802.11n
	IEEE 802.11ac
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n
	• 2.402 – 2.482 GHz
	802.11a/n
	• 4.9 – 4.95 GHz (Japan)
	• 5.15 – 5.25 GHz
	• 5.25 – 5.35 GHz
	• 5.47 – 5.725 GHz
	• 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
	• 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
Modulation	Direct Sequence Spread Spectrum
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security ³	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
	AES-CCMP: 128 bit in hardware
	• 802.1x authentication
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
	WPA2 certification
	• IEEE 802.11i
	Cisco Certified Extensions, all versions through CCX4 and CCX Lite
	• WAPI
Network Architecture	Ad-hoc (Peer to Peer)
Models	Infrastructure (Access Point Required)



Roaming	IEEE 802.11 compliant roaming between access points	
Output Power ²	• 802.11b: +18.5dBm minimum	
_	• 802.11g: +17.5dBm minimum	
	• 802.11a: +18.5dBm minimum	
	• 802.11n HT20(2.4GHz): +15.5dBm minimum	
	• 802.11n HT40(2.4GHz): +14.5dBm minimum	
	• 802.11n HT20(5GHz): +15.5dBm minimum	
	• 802.11n HT40(5GHz): +14.5dBm minimum	
	• 802.11ac VHT80(5GHz): +11.5dBm minimum	
Power Consumption	• Transmit mode2.0 W	
	• Receive mode 1.6 W	
	• Idle mode (PSP) 180 mW (WLAN Associated)	
	• Idle mode 50 mW (WLAN unassociated)	
	Connected Standby 10mW	
	Radio disabled 8 mW	
Power Management	ACPI and PCI Express compliant power management	
	802.11 compliant power saving mode	
Receiver Sensitivity ³	802.11b, 1Mbps: -93.5dBm maximum	
	802.11b, 11Mbps: -84dBm maximum	
	802.11a/g, 6Mbps: -86dBm maximum	
	802.11a/g, 54Mbps: -72dBm maximum	
	802.11n, MCS07: -67dBm maximum	
	802.11n, MCS15: -64dBm maximum	
	802.11ac, MCS0: -84dBm maximum	
	802.11ac, MCS9: -59dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure	
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN	
	MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230: 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating 14° to 158° F (–10° to 70° C)	
	Non-operating	
Humidity	Operating 10% to 90% (non-condensing)	
-	Non-operating 5% to 95% (non-condensing)	
Altitude	Operating 0 to 10,000 ft (3,048 m)	
	Non-operating 0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF; LED White – Radio ON	
-	e/driver release for undates on supported security features	

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology	
Bluetooth® Specification	4.0/4.1/4.2 Compliant
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	BLE: 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)



Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy LE Privacy 1.2 -Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

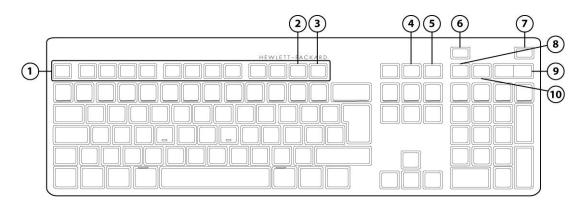


Standard Features and Configurable Components (availability may vary by country)

I/O DEVICES

HP EliteDesk 705 G4 Microtower

HP Conferencing Keyboard



- 1. Function Keys
- 2. F11 Lync or Skype for Business Contact list¹
- 3. F12 Lync or Skype for Business Calendar²
- 4. Share Screen
- 5. Stop Webcam

- 6. End/Decline a Call
- 7. Answer a Call
- 8. Microphone Mute
- 9. Volume Up/Down
- 10. Audio Mute
- 1. Microsoft Lync 2013, or Skype for Business, or Microsoft Outlook 2013 Contact list
- 2. Microsoft Lync 2013, or Skype for Business, or Microsoft Outlook 2013 Calendar

HP USB Premium Keyboard			
	Keys	104, 105 layout (depending upon country)	
Physical Characteristics	Dimensions (L x W x H)	17.04 x 5.55 x 0.52 in (433 x 141 x13.2 mm)	
	Weight	1.54 lb (698ց)	
	Operating voltage	5 VDC, +/-5%	
	Power consumption	35mA (All LED on)	
Electrical	System interface	USB Type A plug connector	
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV	
	EMI - RFI	Conforms to FCC rules for a Class B computing device	
	Keycaps	Low-profile design	
	Switch actuation	60±10g nominal peak force with tactile feedback	
Mechanical	Switch life	10 million keystrokes (Life tester)	
rieciiaiiicat	Switch type	Contamination-resistant switch membrane	
	Key-leveling mechanisms	For all double-wide and greater-length keys	
	Cable length	6 ft (1.8 m)	
Environmental	Acoustics	43-dBA maximum sound pressure level	
Environmental	Operating temperature	50° to 122° F (10° to 50° C)	

	Non-operating temperature	-22° to 140° F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non-condensing at ambient)	
	Operating shock	40 g, six surfaces	
	Non-operating shock	80 g, six surfaces	
	Operating vibration 2-g peak acceleration		
	Non-operating vibration	4-g peak acceleration	
	Drop (out of box) 26 in (66 cm) on carpet, six-drop sequence		
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence	
Approvals	UL, FCC, CE Mark, TUV GS, VCCI,	BSMI, C-Tick, KC	
Ergonomic Compliance	TUVGS		
Kit Contents	Keyboard, QSP		
Warranty Card	Product Notice		

Skylab USB Wired Ke	yboard	
	Keys	104, 105, 106, 107, 109 layout (depending upon country)
Physical Characteristics	Dimensions (L x W x H)	171.97 x 68.35 x 8.27 in (436.8± 1.5 x 137.6± 1.0 x 21.0± 1.0 cm)
	Weight	1.32 lb (0.6± 0.08 kg)
	Operating voltage	4.4-5.25VDC
	Power consumption	50-mA maximum (with 5 VDC power supplied and three LEDs ON)
Electrical	System interface	USB
	ESD	Contact Discharge: 2, 4,6,8KV Air Discharge: 2, 4, 8,10,12.5KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
	Keycaps	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
Mechanical	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
	Microsoft PC 99 - 2001	Mechanically compliant
	Acoustics	43-dBA maximum sound pressure level
Environment-l	Operating temperature	50° to 122° F (10° to 50° C)
Environmental	Non-operating temperature	Minus 30 degress to 60 degress Celsius
	Operating humidity	10% to 90% (non-condensing at ambient)



	Non-operating humidity	20% to 80% (non-condensing at ambient)			
	Operating shock	40 g, six surfaces			
	Non-operating shock	80 g, six surfaces			
	Operating vibration	perating vibration 2-g peak acceleration			
	Non-operating vibration	4-g peak acceleration			
	Drop (out of box)	(out of box) 26 in (66 cm) on carpet, six-drop sequence			
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence			
Approvals	UL, FCC, CE Mark, TUV GS, VCCI,	BSMI, C-Tick, KC			
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and TUVGS				
Kit contents	Keyboard, Installation Guide, Warranty card, Safety and Comfort Guide				

HP USB Premium Mo	ouse		
Dimensions (H x L x W)	4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mmm)		
Weight	0.19lb (90g)		
	Operating temperature	50° to 122°F (10° to 50° C)	
	Non-operating temperature	-22° to 140°F (-30° to 60° C)	
	Operating humidity	10% to 90% (non-condensing at ambient)	
	Non-operating humidity	20% to 80% (non condensing at ambient)	
Environmental	Operating shock	50 g, 6 surfaces	
	Non-operating shock	80 g, 6 surfaces	
	Operating vibration	2 g peak acceleration	
	Non-operating vibration	4 g peak acceleration	
	Operating voltage	5 VDC, +/-5%	
Electrical	Power consumption	12mA	
	Connector	USB 2.0	
Mechanical	Туре	3D mouse (3 keys and wheel)	
rieciiaiiicat	Resolution	800, 1200, 1600 DPI	
	Sensor	Pixart PAN3606DL	
	Tracking acceleration	8G(max), 1G=9.8m/s2	
Tracking speed	Cable length	6 ft (1.8 m)	
	Color	Jack Black	
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, C-Tick, KC	

Standard Features and Configurable Components (availability may vary by country)

HP USB Mouse			
Dimensions (H x L x W)	37mm*115mm*62.9mm		
Weight	90 +10g/- 5 g		
Color	Black		
Connector	USB		
Maskawisal	Resolution	800 DPI sensitivity	
Mechanical	Buttons	Two primary buttons and clickable scroll wheel	

AUDIO/MULTIMEDIA

HP EliteDesk 705 G4 Microtower

Type Integrated

HD Stereo Codec Synaptics CX20632

Audio I/O Ports Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-

out, Microphone-in or Headphone-out port

1 - Headphone port Rear: Line-out

Line-in which is retaskable as a Microphone Input

All ports are 3.5mm and support stereo

2W class D mono amplifier for the internal speaker only. External speakers must be powered

Internal Speaker Amplifier externally

Playback multi-streaming can be enabled in the audio control panel to allow independent audio

Multi-streaming Capable streams to be sent to/from the front and rear jacks or integrated speaker.

Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

Sampling to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes

Standard Features and Configurable Components (availability may vary by country)

HP EliteDesk 705 G4 Small Form Factor Business PC

Type Integrated

HD Stereo Codec Conexant CX20632

Audio I/O Ports Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-

out, Microphone-in or Headphone-out port

1 - Headphone port Rear: Line-out

Line-in which is retaskable as a Microphone Input

All ports are 3.5mm and support stereo

2W class D mono amplifier for the internal speaker only. External speakers must be powered

Internal Speaker Amplifier externally

Playback multi-streaming can be enabled in the audio control panel to allow independent audio

streams to be sent to/from the front and rear jacks or integrated speaker.

Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

Multi-streaming Capable

Sampling

Sampling

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes

HP EliteDesk 705 G4 Desktop Mini Business PC

Type Integrated

HD Stereo Codec Conexant CX20632

Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-

out, Microphone-in or Headphone-out port

1 - Headphone port

Audio I/O Ports All ports are 3.5mm and support stereo

Internal Speaker Amplifier 2W class D mono amplifier for the internal speaker only. External speakers must be powered

Playback multi-streaming can be enabled in the audio control panel to allow independent audio

Multi-streaming Capable streams to be sent to/from the front and rear jacks or integrated speaker.

Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz

to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC

Wavetable Syntheses Yes - Uses OS soft wavetable

Analog Audio Yes

of Channels on Line-Out Stereo (Left & Right channels)

Internal Speaker Yes



Standard Features and Configurable Components (availability may vary by country)

POWER

HP EliteDesk 705 G4 Microtower

UNIT ENVIRONMENT AND OPERATING CONDITIONS

Temperature Range Operating: 5°C ~45°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating: 5% to 90% relative humidity at max inlet temperature

Non Operating: 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50000ft (15240 m)

HP EliteDesk 705 G4 Small Form Factor Business PC

UNIT ENVIRONMENT AND OPERATING CONDITIONS

Temperature Range Operating: 5°C ~50°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft (15240 m)

HP EliteDesk 705 G4 Desktop Mini Business PC

UNIT ENVIRONMENT AND OPERATING CONDITIONS

Temperature Range Operating: 5°C ~35°C

Non-Operating: -40°C ~66°C

Relative Humidity Operating 5% to 90% relative humidity at max inlet temperature

Non-Operating 5% to 90% relative humidity at max inlet temperature

Maximum Altitude Operating: 5000m

(unpressurized) Non-operating: 50,000 ft (15240 m)



	DM	SFF	MT
80 PLUS Platinum		180W active PFC 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V	250W active PFC / 80 PLUS Platinum 400W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)
Operating Voltage Range	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac
Rated Line Frequency	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ
Operating Line Frequency	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ
Rated Input Current	65W≦1.6A 90W≦1.2A 150WW≦2.2A	250W\$A 400W\$.2A	250W≦A 400W≦.2A
-	65W≦1.6A 90W≦1.2A 150WW≨.2A	250W含A 400W≤3.2A	250W含A 400W≤5.2A
DC Output	+19.5V	+12V	+12V
Current Leakage (NFPA 99: 2102)	the ground wire intact with normal polarity, as required for Non-patient Electrical	leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that	normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient
Power Supply Fan	N/A	50mm variable speed	70mm variable speed
Power cord length	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)
External Power Adapter	External power supply 65W EPS, 89% average efficiency at 115V & 230Vac 90W EPS, 89% average efficiency at 115V & 230Vac 150W EPS, 89% average efficiency at 115V & 230Vac	Internal power supply	Internal power supply

Standard Features and Configurable Components (availability may vary by country)

	65W : 113.5mm x 55mm x	200mm x 85mm x 53mm	165mm x 95mm x 73mm
	30mm		
Dimensions	90W : 132.5mm x 57mm x		
Dillielisiolis	30.3mm		
	150W : 167.5mm x 80mm x		
	40.5mm		

WEIGHTS & DIMENSIONS

	<u>DM</u>	<u>SFF</u>	<u>MT</u>
Chassis (W x D x H) Not including bezel	6.97 x 6.89 x 1.35 in 177 x 175 x 34.2mm	3.7 10.6 x 11.7 in 95 x 270 x 296 mm	6.69 x10.79 x 13.3 in 170 x 274 x 338 mm
System Volume	64 cu in 1.05 L	463 cu in 7.6 L	960 cu in 15.74 L
Max System Weight	1.265kg		
Max Supported Weight (desktop orientation)	0	77 lb 35kg	77 lb 35kg
Stand Dimensions	160x117x18.5mm		
Packaging (W x D x H)	19.57 x 5.04 x 8.78 in 497 x 128 x 223 mm	15.71 x 9.06 x 19.65 in 399 x 230 x 499 mm	15.35 x 11.73 x 19.65 x in 390 x 298 x 499 mm
Shipping Weight	2.95 kg 6.49 lb	16.12 lb. 7.32 kg	22.64 lb. 10.28kg
Multipack Packaging (10 units)	20.28x16.54x25 in 515x420x636 mm		
Palletization Profile	18-units per layer 5 or 6 layers max depending on details of air freight 90 or 108 units per pallet depending on details of air freight 45.354 x 39.13 x 75.551 in, 1152 x 994 x 1919 mm (include pallet)	6-units per layer 60 per pallet 47.24 x 39.37 x 94.49 in (including pallet) 10 layer max	6-units per layer 42 per pallet 47.24 x 39.37 x 86.85 in (including pallet) 7 layer max



Technical Specifications – Miscellaneous Features

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode.
 Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software
- 5 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- Clear Password Jumper
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal
- Green Pull Tabs, and Quick Release Latches for easy Identification

Additional Features

Product can be oriented as either a desktop (horizontal) or a tower (vertical)



Technical Specifications – After Market Options

AFTER MARKET OPTIONS

Graphics Solutions	<u>DM</u>	SFF	TWR	Part Number
AMD® Radeon™ R7 430 2GB 2DP Card		X		3TK71AA
AMD® Radeon™ RX550 4GB 2DP Card		X	X	3MQ82AA
HP DisplayPort™ To HDMI True 4k Adapter	X	X	X	2JA63AA
HP DVI Cable Kit		X	X	DC198A
HP HDMI Standard Cable Kit	X	X	X	T6F94AA
HP DisplayPort™ Cable Kit	X	X	X	VN567AA
HP DisplayPort™ To DVI-D Adapter	X	X	X	FH973AA
HP DisplayPort™ To VGA Adapter	Х	X	X	AS615AA

Desktop Mini Accessories	<u>DM</u>	<u>SFF</u>	TWR	Part Number
HP Desktop Mini G3 Port Cover Kit	X			1ZE52AA
HP G4 Mini 2.5-inch SATA Drive Bay Kit	Х			3TK91AA
HP Desktop Mini LockBox V2	X			3EJ57AA
HP Desktop Mini 500GB HDD/I/O Expansion Module	Х			K9Q82AA
HP Desktop Mini DVD-Writer ODD Expansion Module	Х			K9Q83AA
HP Desktop Mini I/O Expansion Module	X			K9Q84AA
HP Desktop Mini Security/Dual VESA Sleeve v2	Х			2JA32AA
HP Desktop Mini Vertical Chassis Stand	X			G1K23AA
HP DM VESA Power Supply Holder Kit	Х			1RL87AA

Desktop Mini Accessories	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>Part Number</u>
Intel® 9260 802.11ac non-vPro PCIe x1 Card		Х	Х	3TK89AA
Realtek 8822BE 802.11ac PCIe x1 Card		X	X	3TK90AA

Data Storage Drives	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>Part Number</u>
HP 256GB SATA TLC Non-SED Solid State Drive	X	X	X	P1N68AA
HP PCIe NVME TLC 256GB SSD M.2 Drive	X	Х	X	1CA51AA
HP PCIe NVME TLC 512GB SSD M.2 Drive	X	X	X	X8U75AA
HP PCIe NVME TLC 512GB SSD PCIe Drive		Х	X	Z4L70AA
HP 500GB 7200PRM SATA 6.0Gb/s 3.5" Hard Drive		Х	X	QK554AA
HP 1TB 7200rpm SATA 6Gb/s 3.5" Hard Drive		X	X	QK555AA
HP SATA SuperMulti JB Drive			X	QS208AA
HP 9.5mm Slim Removable SATA 500GB		X	X	T7G14AA
HP 9.5mm G3 8/6/4 SFF G4 400 SFF/MT DVD Writer		X		1CA53AA

Technical Specifications – After Market Options

Input Devices	<u>DM</u>	<u>SFF</u>	TWR	Part Number
HP USB (Grey) SmartCard CCID Keyboard		X	X	J7H70AA
HP USB Antimicrobial Business Slim Keyboard and Mouse (China Only)		X	X	Z9H50AA
HP USB Buisness Slim CCID SmartCard Keyboard		X	X	Z9H48AA
HP USB Business Slim (Grey) Keyboard (EMEA Only)		X	X	Z9H49AA
HP USB Business Slim Keyboard	Х	Х	X	N3R87AA
HP USB Business Slim Keyboard and Mouse and Mousepad	Х	Х	X	T4E63AA
HP USB Collaboration Keyboard	Х	Х	X	Z9N38AA
HP USB Conferencing Keyboard		X	X	K8P74AA
HP USB Keyboard	Х	Х	X	QY776AA
HP USB Keyboard and Mouse Healthcare Edition				1VD81AA
HP USB Premium Keyboard	Х	Х	X	Z9N40AA
HP USB PS/2 Washable Keyboard & Mouse	Х	X	X	BU207AA
HP Wireless Business Slim Keyboard and Mouse	Х	X	X	N3R88AA
HP Wireless Collaboration Keyboard	Х	X	X	Z9N39AA
HP Wireless Premium Keyboard	Х	X	X	Z9N41AA
HP PS/2 Business Slim Keyboard	Х	X	X	N3R86AA
HP USB Grey v2 Mouse (EMEA only)		X	Х	Z9H74AA
HP USB Premium Mouse		X	Х	1JR32AA
HP PS/2 Mouse	Х	Х	Х	QY775AA
HP USB 1000dpi Laser Mouse	Х	X	Х	QY778AA
HP USB Hardened Mouse		Х	Х	P1N77AA
HP USB Mouse	X	Х	Х	QY777AA

System Memory	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>Part Number</u>
HP 4GB DDR4-2666 DIMM		X	X	3TK85AA
HP 8GB DDR4-2666 DIMM		X	X	3TK87AA
HP 16GB DDR4-2666 DIMM		X	X	3TK83AA
HP 4GB DDR4-2666 SODIMM	X			3TK86AA
HP 8GB DDR4-2666 SODIMM	Х			3TK88AA
HP 16GB DDR4-2666 SODIMM	X			3TK84AA

Multimedia Devices	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>Part Number</u>
HP Business Headset v2	Х	Х	X	T4E61AA
HP USB Business Speakers v2	Х	Х	X	N3R89AA

Security Devices	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>Part Number</u>
HP Solenoid Lock & Hood Sensor (MT)			X	J6L42AA
HP Business PC Security Lock v3 Kit		Х	X	3XJ17AA
HP Dual Head Keyed Cable Lock	Х	Х	X	T1A64AA



Technical Specifications – After Market Options

HP Keyed Cable Lock 10mm	X	X	X	T1A62AA
HP Master Keyed Cable Lock 10mm	Х	X	X	T1A63AA

Stands and Accessories	<u>DM</u>	<u>SFF</u>	TWR	Part Number
HP B300 PC Mounting Bracket	X			2DW53AA
HP B500 PC Mounting Bracket	X			2DW52AA
HP Single Monitor Arm	Х			BT861AA

I/O Devices	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	Part Number
HP DisplayPort™ Port Flex IO	X	X	X	3TK72AA
HP HDMI Port Flex IO (400/600/800)	X	X	X	3TK74AA
HP Type-C™ USB 3.1 Gen2 Port Flex IO	X	X	X	3TK78AA
HP VGA Port Flex IO	Х	X	X	3TK80AA
HP Serial Port Flex IO	X	X	X	3TK76AA
HP Internal Serial Port (400)		X	X	3TK81AA
HP PCIe x1 Parallel Port Card		X	X	N1M40AA
HP 800/600/400 G3 Serial/ PS/2 Adapter		X	X	1VD82AA



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Change Log

Date	Version History	Action	Description of Change
June 20, 2018	From v1 to v2	Update	Weights & Dimensions
June 28, 2018	From v2 to v3	Added	Environmental tab
July 19, 2018	From v3 to v4	Added	Note for SATA Drive Bracket added to Internal Slots and Ports section

